



MOTOROLA

MC1377

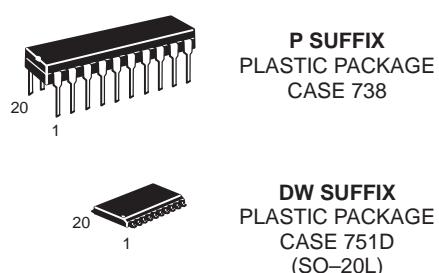
## Color Television RGB to PAL/NTSC Encoder

The MC1377 will generate a composite video from baseband red, green, blue, and sync inputs. On board features include: a color subcarrier oscillator; voltage controlled 90° phase shifter; two double sideband suppressed carrier (DSBSC) chroma modulators; and RGB input matrices with blanking level clamps. Such features permit system design with few external components and accordingly, system performance comparable to studio equipment with external components common in receiver systems.

- Self-contained or Externally Driven Reference Oscillator
- Chroma Axes, Nominally 90° ( $\pm 5^\circ$ ), are Optionally Trimable
- PAL/NTSC Compatible
- Internal 8.2 V Regulator

### COLOR TELEVISION RGB to PAL/NTSC ENCODER

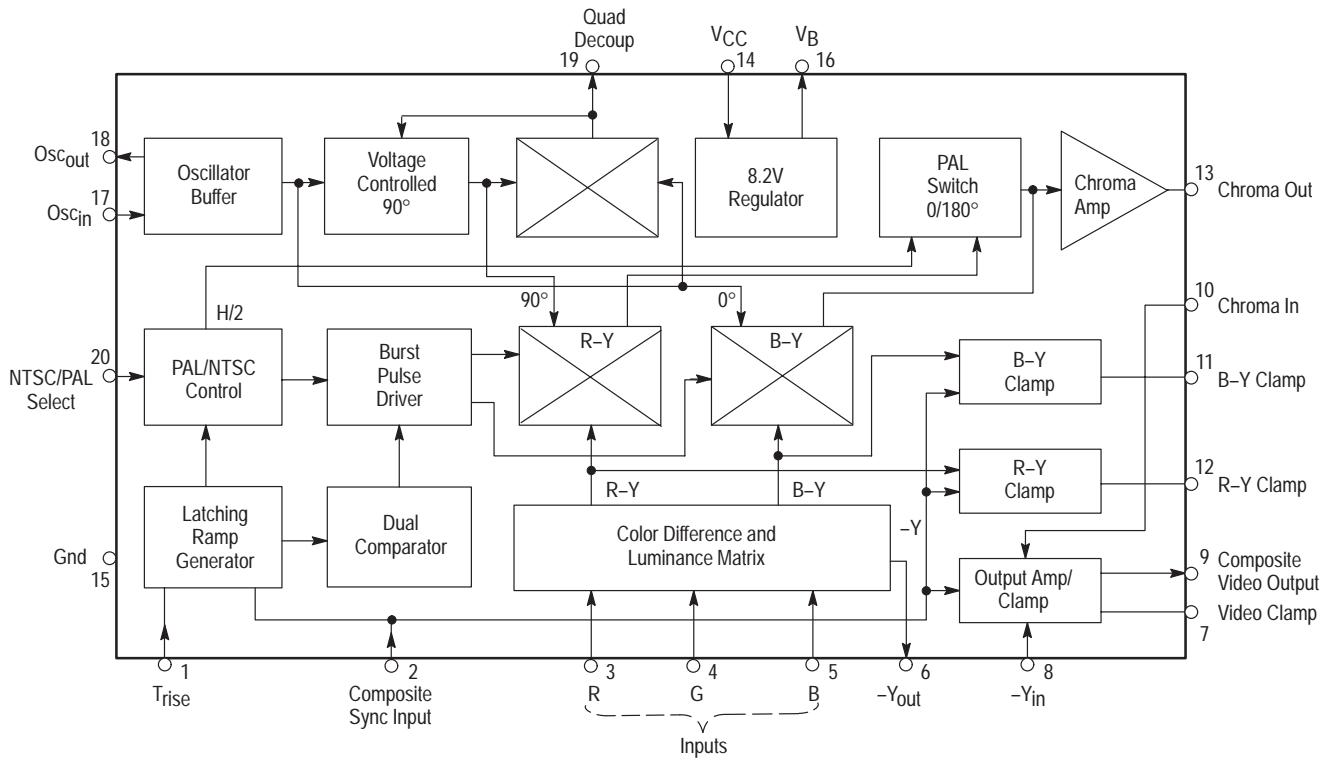
#### SEMICONDUCTOR TECHNICAL DATA



#### ORDERING INFORMATION

Device	Operating Temperature Range	Package
MC1377DW	TA = 0° to +70°C	SO-20L
MC1377P		Plastic DIP

Figure 1. Representative Block Diagram



## MAXIMUM OPERATING CONDITIONS

Rating	Symbol	Value	Unit
Supply Voltage	$V_{CC}$	15	Vdc
Storage Temperature	$T_{stg}$	-65 to +150	°C
Power Dissipation Package Derate above 25°C	$P_D$	1.25 10	W mW/°C
Operating Temperature	$T_A$	0 to +70	°C

## RECOMMENDED OPERATING CONDITIONS

Characteristics	Min	Typ	Max	Unit
Supply Voltage	10	12	14	Vdc
$I_B$ Current (Pin 16)	0	-	-10	mA
Sync, Blanking Level (DC level between pulses, see Figure 9e) Sync Tip Level (see Figure 9e) Sync Pulse Width (see Figure 9e)	1.7 -0.5 2.5	- 0 -	8.2 0.9 5.2	Vdc μs
R, G, B Input (Amplitude) R, G, B Peak Levels for DC Coupled Inputs, with Respect to Ground	- 2.2	1.0 -	- 4.4	$V_{pp}$ V
Chrominance Bandwidth (Non-comb Filtered Applications), (6 dB)	0.5	1.5	2.0	MHz
Ext. Subcarrier Input (to Pin 17) if On-Chip Oscillator is not used.	0.5	0.7	1.0	$V_{pp}$

ELECTRICAL CHARACTERISTICS ( $V_{CC} = 12$  Vdc,  $T_A = 25^\circ\text{C}$ , circuit of Figure 7, unless otherwise noted.)

Characteristics	Pins	Symbol	Min	Typ	Max	Unit
<b>SUPPLY CURRENT</b>						
Supply Current into $V_{CC}$ , No Load, on Pin 9. Circuit Figure 7	$V_{CC} = 10$ V $V_{CC} = 11$ V $V_{CC} = 12$ V $V_{CC} = 13$ V $V_{CC} = 14$ V	$I_{CC}$	- - 20 - -	33 34 35 36 37	- - 40 - -	mA

**VOLTAGE REGULATOR**

$V_B$ Voltage ( $I_B = -10$ mA, $V_{CC} = 12$ V, Figure 7) Load Regulation ( $0 < I_B \leq 10$ mA, $V_{CC} = 12$ V) Line Regulation ( $I_B = 0$ mA, $10$ V < $V_{CC} < 14$ V)	16	$V_B$ Regload Regline	7.7 -20 -	8.2 120 4.5	8.7 +30 -	Vdc mV mV/V
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**OSCILLATOR AND MODULATION**

Oscillator Amplitude with 3.58 MHz/4.43 MHz crystal	17	Osc	-	0.6	-	$V_{pp}$
Subcarrier Input: Resistance at 3.58 MHz 4.43 MHz	17	$R_{osc}$	-	5.0	-	kΩ
		$C_{osc}$	-	2.0	-	pF
Modulation Angle (R-Y) to (B-Y) Angle Adjustment (R-Y) DC Bias Voltage	- 19 19	$\emptyset_m$ $\Delta\emptyset_m$ $V_{19}$	- - -	±5 0.25 6.4	- - -	Deg Deg/μA Vdc

**CHROMINANCE AND LUMINANCE**

Chroma Input DC Level Chroma Input Level for 100% Saturation	10	$V_{in}$	- -	4.0 0.7	-	Vdc $V_{pp}$
Chroma Input: Resistance Capacitance		$R_{in}$ $C_{in}$	- -	10 2.0	-	kΩ pF
Chroma DC Output Level Chroma Output Level at 100% Saturation	13	$V_{out}$	8.9 -	10 1.0	10.9	Vdc $V_{pp}$
		$R_{out}$	-	50	-	Ω
Luminance Bandwidth (-3.0 dB), Less Delay Line	9	$BW_{Luma}$	-	8.0	-	MHz

ELECTRICAL CHARACTERISTICS (V<sub>CC</sub> = 12 Vdc, T<sub>A</sub> = 25°C, circuit of Figure 7, unless otherwise noted.)

Characteristics	Pins	Symbol	Min	Typ	Max	Unit
<b>VIDEO INPUT</b>						
R, G, B Input DC Levels	3, 4, 5	RGB	2.8	3.3	3.8	Vdc
R, G, B Input for 100% Color Saturation			—	1.0	—	V <sub>pp</sub>
R, G, B Input: Resistance Capacitance		R <sub>RGB</sub> C <sub>RGB</sub>	8.0 —	10 2.0	17 —	kΩ pF
Sync Input Resistance (1.7 V < Input < 8.2)	2	Sync	—	10	—	kΩ

**COMPOSITE VIDEO OUTPUT**

Composite Output, 100% Saturation (see Figure 8d)	Sync Luminance Chroma Burst	9	C <sub>Vout</sub>	— — — —	0.6 1.4 1.7 0.6	— — — —	V <sub>pp</sub>
Output Impedance (Note 1)			R <sub>video</sub>	—	50	—	Ω
Subcarrier Leakage in Output (Note 2)			V <sub>lk</sub>	—	20	—	mV <sub>pp</sub>

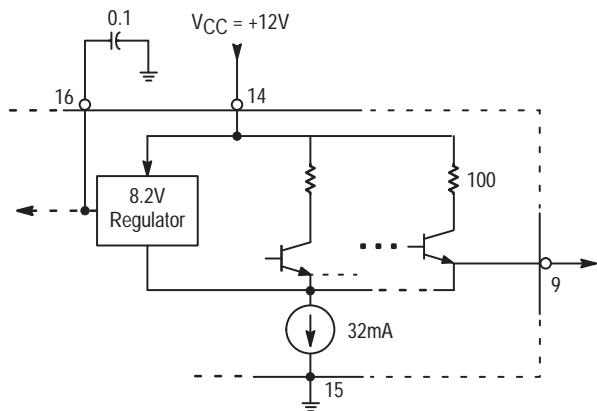
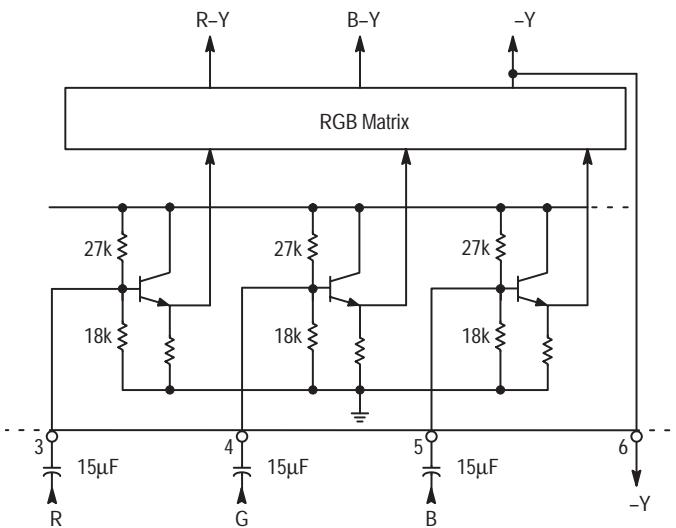
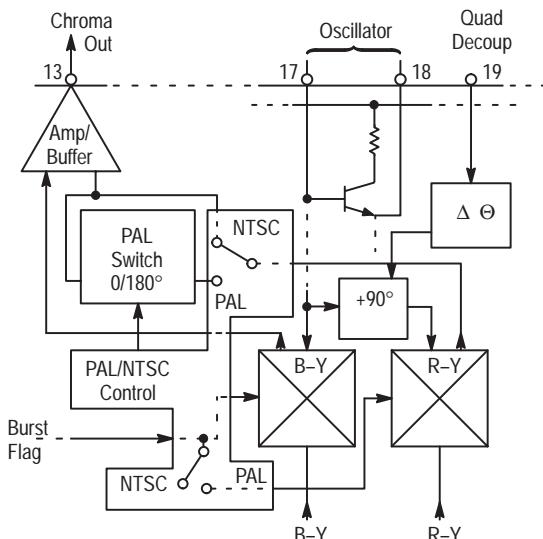
**NOTES:** 1. Output Impedance can be reduced to less than 10 Ω by using a 150 Ω output load from Pin 9 to ground. Power supply current will increase to about 60 mA.

2. Subcarrier leakage can be reduced to less than 10 mV with optional circuitry (see Figure 12).

**PIN FUNCTION DESCRIPTIONS**

Symbol	Pin	Description
t <sub>r</sub>	1	External components at this pin set the rise time of the internal ramp function generator (see Figure 10).
Sync	2	Composite sync input. Presents 10 kΩ resistance to input.
R	3	Red signal input. Presents 10 kΩ impedance to input. 1.0 V <sub>pp</sub> required for 100% saturation.
G	4	Green signal input. Presents 10 kΩ impedance to input. 1.0 V <sub>pp</sub> required for 100% saturation.
B	5	Blue signal Input. Presents 10 kΩ impedance to input. 1.0 V <sub>pp</sub> required for 100% saturation.
-Y <sub>out</sub>	6	Luma (-Y) output. Allows external setting of luma delay time.
V <sub>clamp</sub>	7	Video Clamp pin. Typical connection is a 0.01 μF capacitor to ground.
-Y <sub>in</sub>	8	Luma (-Y) input. Presents 10 kΩ input impedance.
C <sub>Vout</sub>	9	Composite Video output. 50 Ω output impedance.
ChromaIn	10	Chroma input. Presents 10 kΩ input impedance.
B-Yclamp	11	B-Y clamp. Clamps B-Y during blanking with a 0.1 μF capacitor to ground. Also used with R-Y clamp to null residual color subcarrier in output.
R-Yclamp	12	R-Y clamp. Clamps R-Y during blanking with a 0.1 μF capacitor to ground. Also used with B-Y clamp to null residual color subcarrier in output.
ChromaOut	13	Chroma output. 50 Ω output impedance.
V <sub>CC</sub>	14	Power supply pin for the IC; +12, ± 2.0 V, required at 35 mA (typical).
Gnd	15	Ground pin.
V <sub>B</sub>	16	8.2 V reference from an internal regulator capable of delivering 10 mA to external circuitry.
Oscin	17	Oscillator input. A transistor base presents 5.0 kΩ to an external subcarrier input, or is available for constructing a Colpitts oscillator (see Figure 4).
Oscout	18	Oscillator output. The emitter of the transistor, with base access at Pin 17, is accessible for completing the Colpitts oscillator. See Figure 4.
Ø <sub>m</sub>	19	Quad decoupler. With external circuitry, R-Y to B-Y relative angle errors can be corrected. Typically, requires a 0.01 μF capacitor to ground.
NTSC/PAL Select	20	NTSC/PAL switch. When grounded, the MC1377 is in the NTSC mode; if unconnected, in the PAL mode.

## FUNCTIONAL DESCRIPTION

**Figure 2. Power Supply and  $V_B$** **Figure 3. RGB Input Circuitry****Figure 4. Chroma Section****Power Supply and  $V_B$  (8.2 V Regulator)**

The MC1377 pin for power supply connection is Pin 14. From the supply voltage applied to this pin, the IC biases internal output stages and is used to power the 8.2 V internal regulator ( $V_B$  at Pin 16) which biases the majority of internal circuitry. The regulator will provide a nominal 8.2 V and is capable of 10 mA before degradation of performance. An equivalent circuit of the supply and regulator is shown in Figure 2.

**R, G, B Inputs**

The RGB inputs are internally biased to 3.3 V and provide 10 kΩ of input impedance. Figure 3 shows representative input circuitry at Pins 3, 4, and 5.

The input coupling capacitors of 15 μF are used to prevent tilt during the 50/60 Hz vertical period. However, if it is desired to avoid the use of the capacitors, then inputs to Pins 3, 4, and 5 can be dc coupled provided that the signal levels are always between 2.2 V and 4.4 V.

After input, the separate RGB information is introduced to the matrix circuitry which outputs the R-Y, B-Y, and -Y signals. The -Y information is routed out at Pin 6 to an external delay line (typically 400 ns).

**DSBSC Modulators and 3.58 MHz Oscillator**

The R-Y and B-Y outputs (see (B-Y)/(R-Y) Axes versus I/Q Axes, Figure 22) from the matrix circuitry are amplitude modulated onto the 3.58/4.43 MHz subcarrier. These signals are added and color burst is included to produce composite chroma available at Pin 13. These functions plus others, depending on whether NTSC or PAL operation is chosen, are performed in the chroma section. Figure 4 shows a block diagram of the chroma section.

The MC1377 has two double balanced mixers, and regardless of which mode is chosen (NTSC or PAL), the mixers always perform the same operation. The B-Y mixer modulates the color subcarrier directly, the R-Y mixer receives a 90° phase shifted color subcarrier before being modulated by the R-Y baseband information. Additional operations are then performed on these two signals to make them NTSC or PAL compatible.

In the NTSC mode, the NTSC/PAL control circuitry allows an inverted burst of 3.58 MHz to be added only to the B-Y signal. A gating pulse or "burst flag" from the timing section permits color burst to be added to the B-Y signal. This color burst is 180° from the B-Y signal and 90° away from the R-Y signal (see Figure 22) and permits decoding of the color information. These signals are then added and amplified before being output, at Pin 13, to be bandpassed and then reintroduced to the IC at Pin 10.

In the PAL mode, NTSC/PAL control circuitry allows an inverted 4.43 MHz burst to be added to both R-Y and B-Y equally to produce the characteristic PAL 225°/135° burst phase. Also, the R-Y information is switched alternately from 180° to 0° of its original position and added to the B-Y information to be amplified and output.

### Timing Circuitry

The composite sync input at Pin 2 performs three important functions: it provides the timing (but not the amplitude) for the sync in the final output; it drives the black level clamps in the modulators and output amplifier; and it triggers the ramp generator at Pin 1, which produces burst envelope and PAL switching. A representative block diagram of the timing circuitry is shown in Figure 5.

In order to produce a color burst, a burst envelope must be generated which "gates" a color subcarrier into the R-Y and B-Y modulators. This is done with the ramp generator at Pin 1.

The ramp generator at Pin 1 is an R-C type in which the pin is held low until the arrival of the *leading* edge of sync. The rising ramp function, with time constant  $R-C$ , passes through two level sensors – the first one starts the gating pulse and the second stops it (see Figure 10). Since the "early" part of the exponential is used, the timing provided is relatively accurate from chip-to-chip and assembly-to-assembly. Fixed components are usually adequate. The ramp continues to rise for more than half of the line interval, thereby inhibiting burst generation on "half interval" pulses on vertical front and back porches. The ramp method will produce burst on the vertical front and back "porches" at full line intervals.

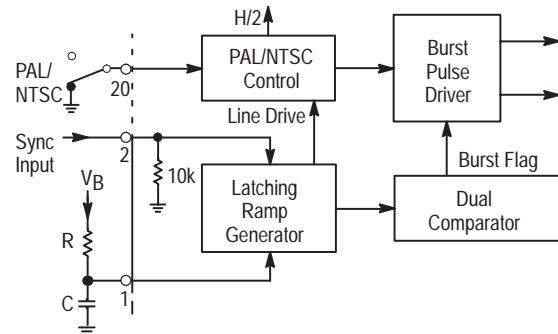
### R-Y, B-Y Clamps and Output Clamp/Amplifier

The sync signal, shown in the block diagram of Figure 6, drives the R-Y and B-Y clamps which clamp the R-Y and B-Y signals to reference black during the blanking periods. The output amplifier/clamp provides this same function plus combines and amplifies the chroma and luma components for composite video output.

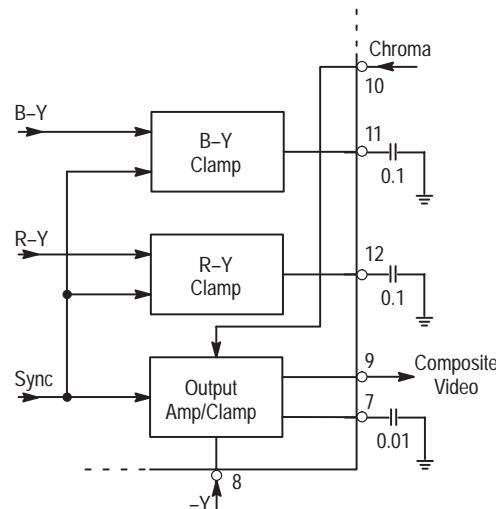
### Application Circuit

Figure 7 illustrates the block diagram of the MC1377 and the external circuitry required for typical operation.

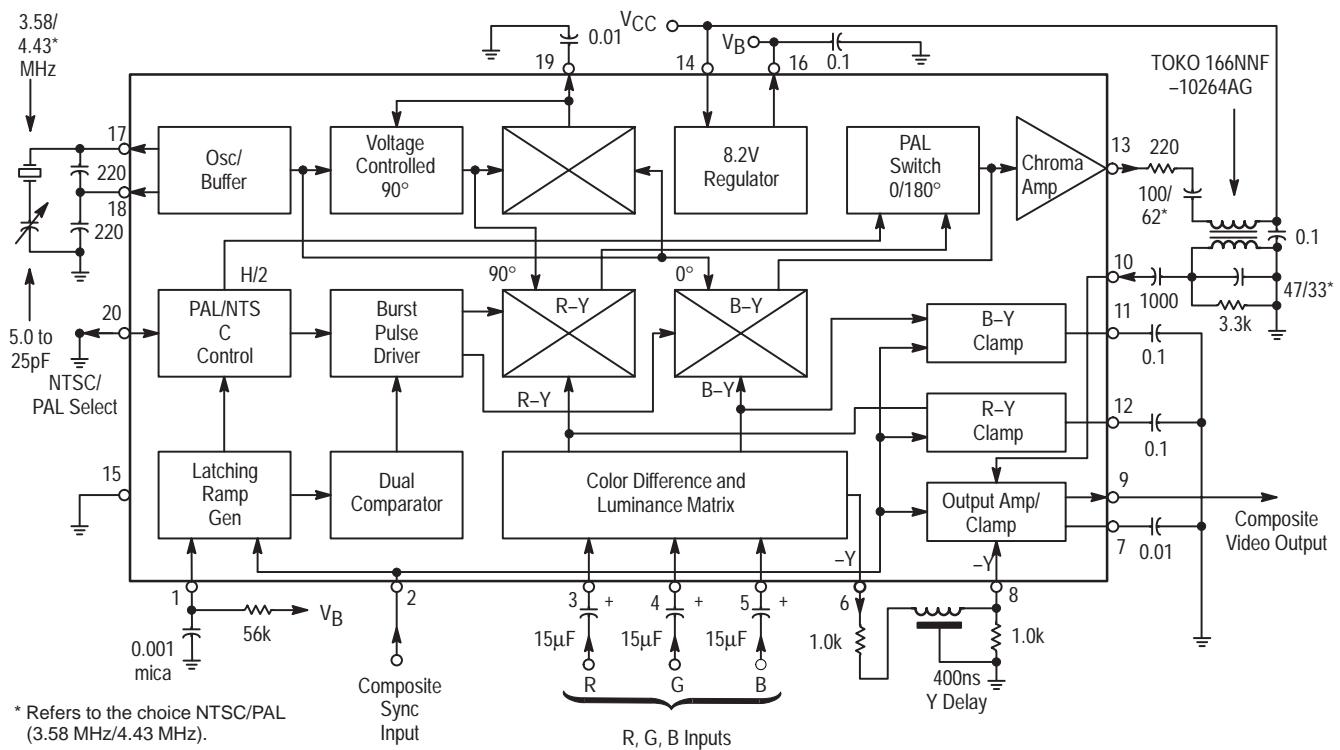
**Figure 5. Timing Circuitry**



**Figure 6. R-Y, B-Y and Output Amplifier Clamps**



**Figure 7. Block Diagram and Application Circuit**



\* Refers to the choice NTSC/PAL (3.58 MHz/4.43 MHz).

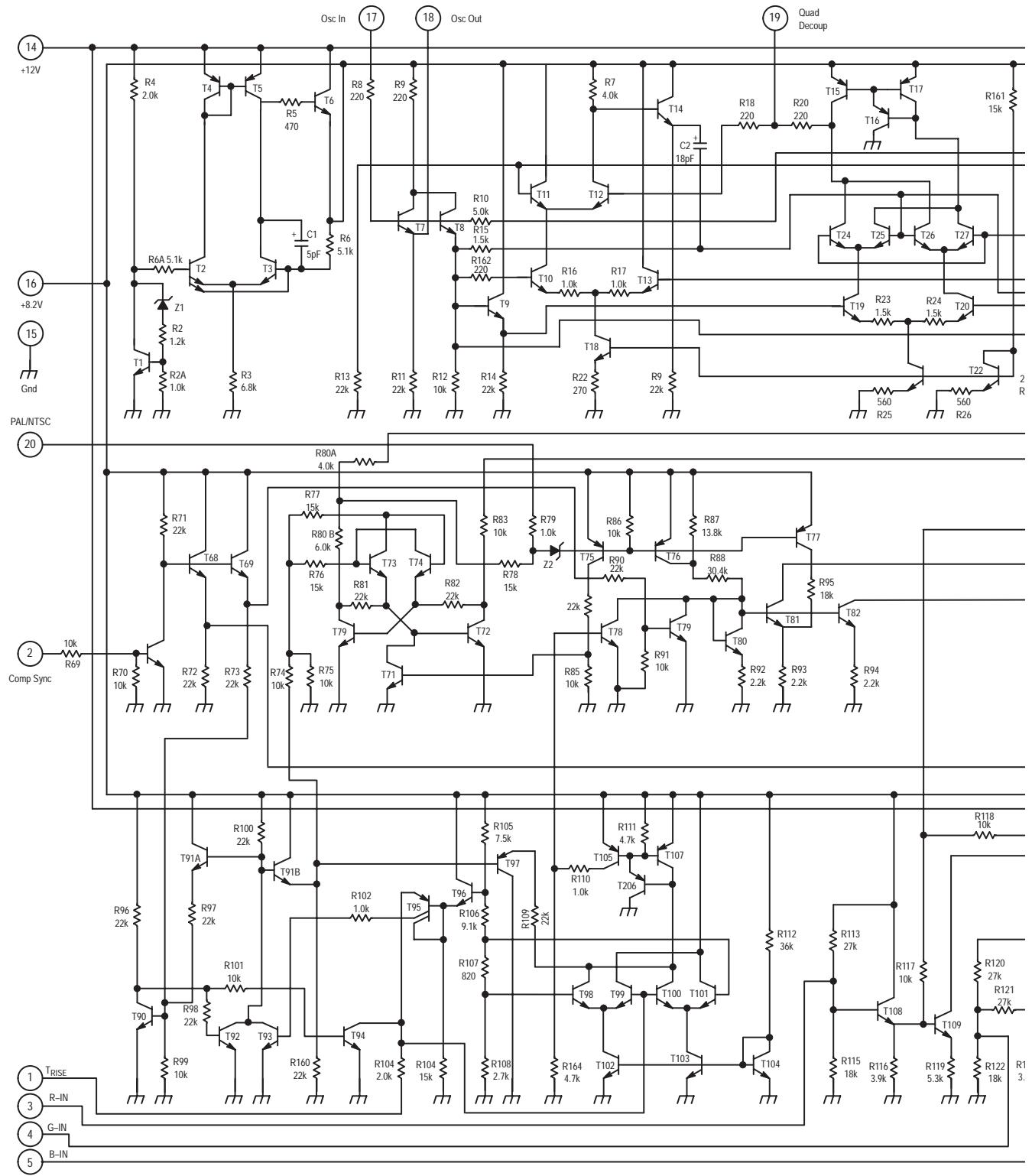
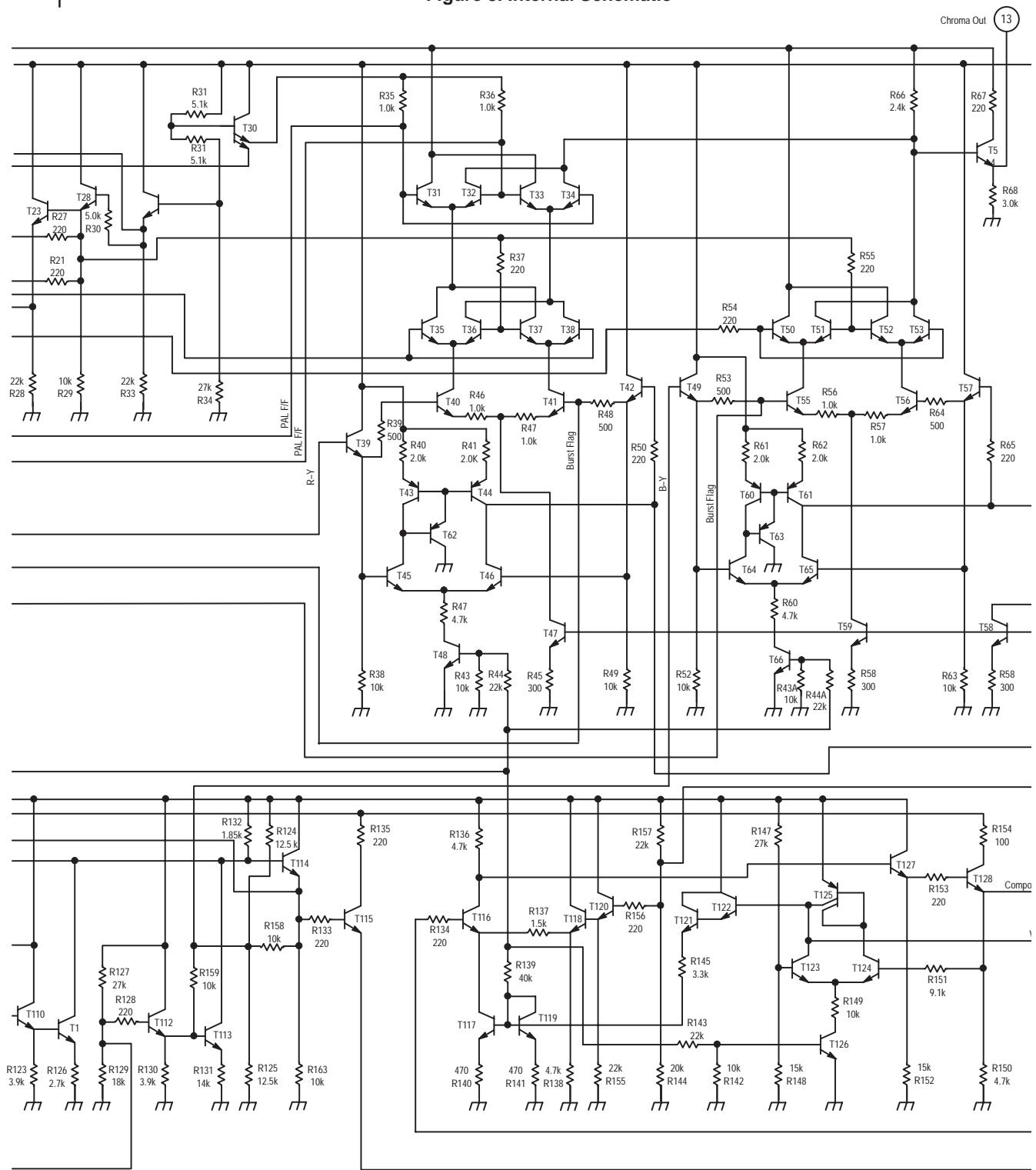
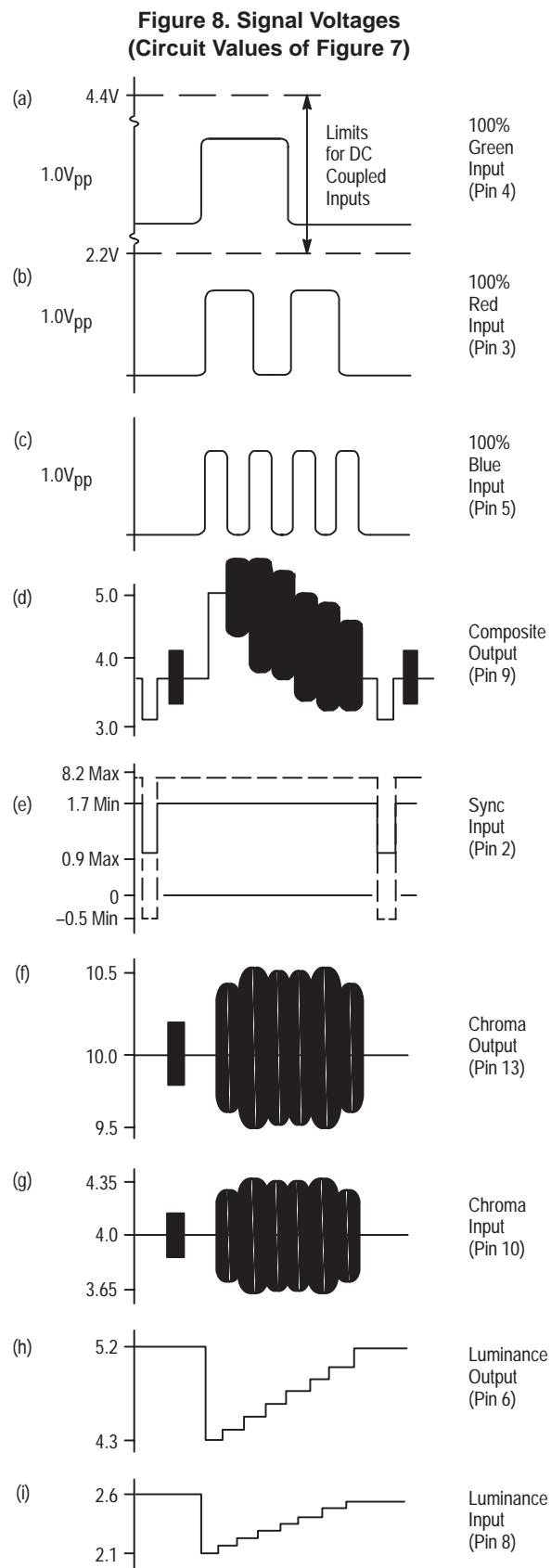


Figure 8. Internal Schematic



## APPLICATION INFORMATION

**R, G, B Input Levels**

The signal levels into Pins 3, 4, 5 should be 1.0 V<sub>pp</sub> for fully saturated, standard composite video output levels as shown in Figure 9(d). The inputs require 1.0 V<sub>pp</sub> since the internally generated sync pulse and color burst are at fixed and predetermined amplitudes.

Further, it is essential that the portion of each input which occurs during the sync interval represent black for that input since that level will be clamped to reference black in the color modulators and output stage. This implies that a refinement, such as a difference between black and blanking levels, must be incorporated in the RGB input signals.

If Y, R-Y, B-Y and burst flag components are available and the MC1377 is operating in NTSC, inputs may be as follows: the Y component can be coupled through a 15 pF capacitor to Pins 3, 4 and 5 tied together; the (-[R-Y]) component can be coupled to Pin 12 through a 0.1  $\mu$ F capacitor, and the (-[B-Y]) and burst flag components can be coupled to Pin 11 in a similar manner.

**Sync Input**

As shown in Figure 9(e), the sync input amplitude can be varied over a wide latitude, but will require bias pull-up from most sync sources. The important requirements are:

- 1) The voltage level between sync pulses must be between 1.7 V and 8.2 V, see Figure 9(e).
- 2) The voltage level for the sync tips must be between +0.9 V and -0.5 V, to prevent substrate leakage in the IC, see Figure 9(e).
- 3) The width of the sync pulse should be no longer than 5.2  $\mu$ s and no shorter than 2.5  $\mu$ s.

For PAL operation, correctly serrated vertical sync is necessary to properly trigger the PAL divider. In NTSC mode, simplified "block" vertical sync can be used but the loss of proper horizontal timing may cause "top hook" or "flag waving" in some monitors. An interesting note is that composite video can be used directly as a sync signal, provided that it meets the sync input criteria.

**Latching Ramp (Burst Flag) Generator**

The recommended application is to connect a close tolerance (5%) 0.001  $\mu$ F capacitor from Pin 1 to ground and a resistor of 51 k $\Omega$  or 56 k $\Omega$  from Pin 1 to V<sub>B</sub> (Pin 16). This will produce a burst pulse of 2.5  $\mu$ s to 3.5  $\mu$ s in duration, as shown in Figure 10. As the ramp on Pin 1 rises toward the charging voltage of 8.2 V, it passes first through a burst "start threshold" at 1.0 V, then a "stop threshold" at 1.3 V, and finally a ramp reset threshold at 5.0 V. If the resistor is reduced to 43 k $\Omega$ , the ramp will rise more quickly, producing a narrower and earlier burst pulse (starting approx. 0.4  $\mu$ s after sync and about 0.6  $\mu$ s wide). The burst will be wider and later if the resistor is raised to 62 k $\Omega$ , but more importantly, the 5.0 V reset point may not be reached in one full line interval, resulting in loss of alternate burst pulses.

As mentioned earlier, the ramp method does produce burst at full line intervals on the "vertical porches." If this is not desired, and the MC1377 is operating in the NTSC mode, burst flag may be applied to Pin 1 provided that the tip of the

pulse is between 1.0 Vdc and 1.3 Vdc. In PAL mode this method is not suitable, since the ramp isn't available to drive the PAL flip-flop. Another means of inhibiting the burst pulse is to set Pin 1 either above 1.3 Vdc or below 1.0 Vdc for the duration that burst is not desired.

### Color Reference Oscillator/Buffer

As stated earlier in the general description, there is an on-board common collector Colpitts color reference oscillator with the transistor base at Pin 17 and the emitter at Pin 18. When used with a common low-cost TV crystal and capacitive divider, about 0.6 V<sub>pp</sub> will be developed at Pin 17. The frequency adjustment can be done with a series 30 pF trimmer capacitor over a total range of about 1.0 kHz. Oscillator frequency should be adjusted for each unit, keeping in mind that most monitors and receivers can pull in 1200 Hz.

If an external color reference is to be used exclusively, it must be continuous. The components on Pins 17 and 18 can be removed, and the external source capacitively coupled into Pin 17. The input at Pin 17 should be a sine wave with amplitude between 0.5 V<sub>pp</sub> and 1.0 V<sub>pp</sub>.

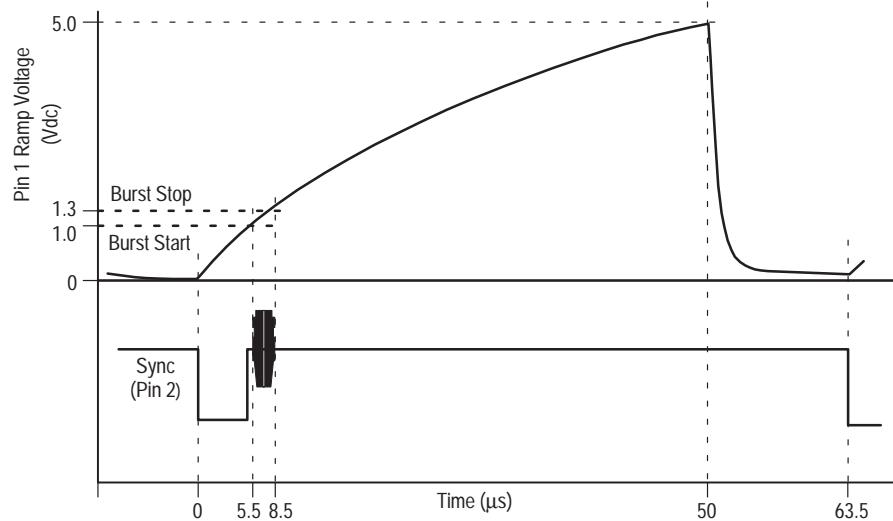
Also, it is possible to do both; i.e., let the oscillator "free run" on its own crystal and override with an external source. An extra coupling capacitor of 50 pF from the external source to Pin 17 was adequate with the experimentation attempted.

### Voltage Controlled 90°

The oscillator drives the (B-Y) modulator and a voltage controlled phase shifter which produces an oscillator phase of  $90^\circ \pm 5^\circ$  at the (R-Y) modulator. In most situations, the result of an error of  $5^\circ$  is very subtle to all but the most expert eye. However, if it is necessary to adjust the angle to better accuracy, the circuit shown in Figure 11 can be used.

Pulling Pin 19 up will increase the (R-Y) to (B-Y) angle by about  $0.25^\circ/\mu\text{A}$ . Pulling Pin 19 down reduces the angle by the same sensitivity. The nominal Pin 19 voltage is about 6.3 V, so even though it is unregulated, the 12 V supply is best for good control. For effective adjustment, the simplest approach is to apply RGB color bar inputs and use a vectorscope. A simple bar generator giving R, G, and B outputs is shown in Figure 26.

**Figure 9. Ramp/Burst Gate Generator**



### Residual Feedthrough Components

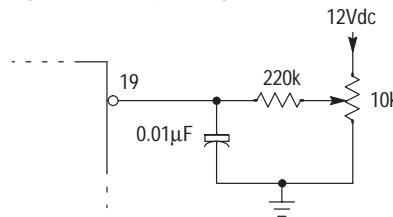
As shown in Figure 9(d), the composite output at Pin 9 for fully saturated color bars is about 2.6 V<sub>pp</sub>, output with full chroma on the largest bars (cyan and red) being 1.7 V<sub>pp</sub>. The typical device, due to imperfections in gain, matrixing, and modulator balance, will exhibit about 20 mV<sub>pp</sub> residual color subcarrier in both white and black. Both residuals can be reduced to less than 10 mV<sub>pp</sub> for the more exacting applications.

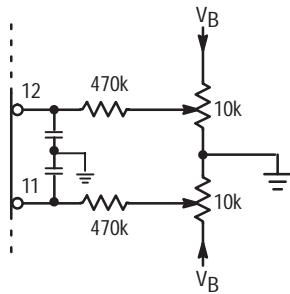
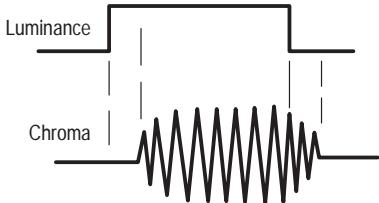
The subcarrier feedthrough in black is due primarily to imbalance in the modulators and can be nulled by sinking or sourcing small currents into clamp Pins 11 and 12 as shown in Figure 12. The nominal voltage on these pins is about 4.0 Vdc, so the 8.2 V regulator is capable of supplying a pull up source. Pulling Pin 11 down is in the  $0^\circ$  direction, pulling it up is towards  $180^\circ$ . Pulling Pin 12 down is in the  $90^\circ$  direction, pulling it up is towards  $270^\circ$ . Any direction of correction may be required from part to part.

White carrier imbalance at the output can only be corrected by juggling the relative levels of R, G, and B inputs

for perfect balance. Standard devices are tested to be within 5% of balance at full saturation. Black balance should be adjusted first, because it affects all levels of gray scale equally. There is also usually some residual baseband video at the chroma output (Pin 13), which is most easily observed by disabling the color oscillator. Typical devices show 0.4 V<sub>pp</sub> of residual luminance for saturated color bar inputs. This is not a major problem since Pin 13 is always coupled to Pin 10 through a bandpass or a high pass filter, but it serves as a warning to pay proper attention to the coupling network.

**Figure 10. Adjusting Modulator Angle**



**Figure 11. Nulling Residual Color in Black****Figure 12. Delay of Chroma Information**

### The Chroma Coupling Circuits

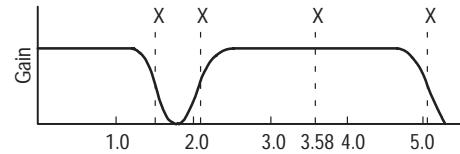
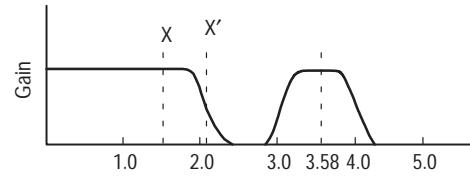
With the exception of S-VHS equipped monitors and receivers, it is generally true that most monitors and receivers have color IF 6.0 dB bandwidths limited to approximately  $\pm 0.5$  MHz. It is therefore recommended that the encoder circuit should also limit the chroma bandwidth to approximately  $\pm 0.5$  MHz through insertion of a bandpass circuit between Pin 13 and Pin 10. However, if S-VHS operation is desired, a coupling circuit which outputs the composite chroma directly for connection to a S-VHS terminal is given in the S-VHS application (see Figure 19).

For proper color level in the video output, a  $\pm 0.5$  MHz bandwidth and a midband insertion loss of 3.0 dB is desired. The bandpass circuit shown in Figure 7, using the TOKO fixed tuned transformer, couples Pin 10 to Pin 13 and gives this result. However, this circuit introduces about 350 ns of delay to the chroma information (see Figure 13). This must be accounted for in the luminance path.

A 350 ns delay results in a visible displacement of the color and black and white information on the final display. The solution is to place a delay line in the luminance path from Pins 6 to 8, to realign the two components. A normal TV receiver delay line can be used. These delay lines are usually of 1.0 k $\Omega$  to 1.5 k $\Omega$  characteristic impedance, and the resistors at Pins 6 and 8 should be selected accordingly. A very compact, lumped constant delay line is available from TDK (see Figure 25 for specifications). Some types of delay lines have very low impedances (approx. 100  $\Omega$ ) and should not be used, due to drive and power dissipation requirements.

In the event of very low resolution RGB, the transformer and the delay line may be omitted from the circuit. Very low resolution for the MC1377 can be considered RGB information of less than 1.5 MHz. However, in this situation, a bandwidth reduction scheme is still recommended due to the response of most receivers.

Figure 14(a) shows the output of the MC1377 with low resolution RGB inputs. If no bandwidth reduction is employed then a monitor or receiver with frequency response shown in Figure 14(b), which is fairly typical of non-comb filtered monitors and receivers, will detect an incorrect luma sideband at X'. This will result in cross-talk in the form of chroma information in the luma channel. To avoid this situation, a simpler bandpass circuit as shown in Figure 15(a), can be used.

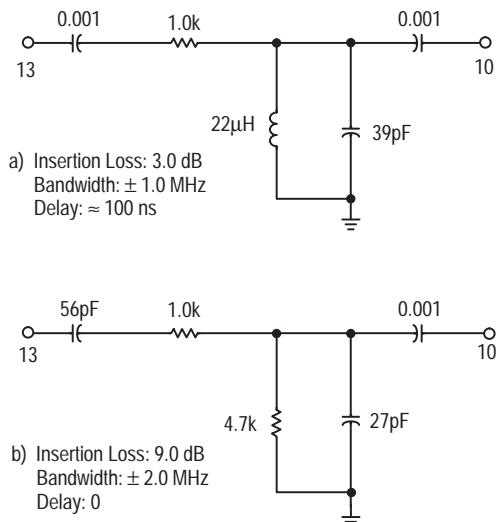
**Figure 13. MC1377 Output with Low Resolution RGB Inputs****(a) Encoder Output with Low Resolution Inputs and No Bandpass Transformer****(b) Standard Receiver Response**

A final option is shown in Figure 15(b). This circuit provides very little bandwidth reduction, but enough to remove the chroma to luma feedthrough, with essentially no delay. There is, however, about a 9 dB insertion loss from this network.

It will be left to the designer to decide which, if any, compromises are acceptable. Color bars viewed on a good monitor can be used to judge acceptability of step luminance/chrominance alignment and step edge transients, but signals containing the finest detail to be encountered in the system must also be examined before settling on a compromise.

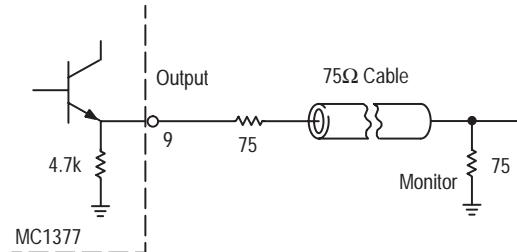
### The Output Stage

The output amplifier normally produces about 2.0 V<sub>pp</sub> and is intended to be loaded with 150  $\Omega$  as shown in Figure 16. This provides about 1.0 V<sub>pp</sub> into 75  $\Omega$ , an industry standard level (RS-343). In some cases, the input to the monitor may be through a large coupling capacitor. If so, it is necessary to connect a 150  $\Omega$  resistor from Pin 9 to ground to provide a low impedance path to discharge the capacitor. The nominal average voltage at Pin 9 is over 4.0 V. The 150  $\Omega$  dc load causes the current supply to rise another 30 mA (to approximately 60 mA total into Pin 14). Under this (normal) condition the total device dissipation is about 600 mW. The calculated worst case die temperature rise is 60°C, but the typical device in a test socket is only slightly warm to the touch at room temperature. The solid copper 20-pin lead frame in a printed circuit board will be even more effectively cooled.

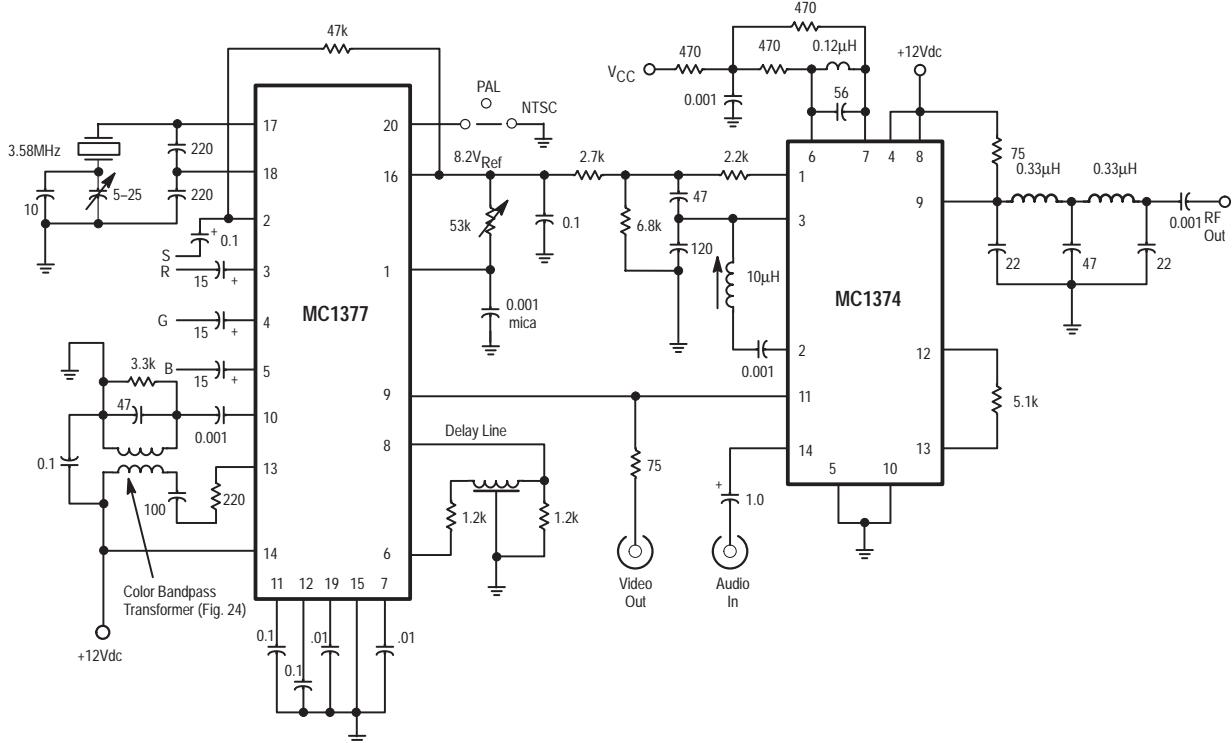
**Figure 14. Optional Chroma Coupling Circuits****Power Supplies**

The MC1377 is designed to operate from an unregulated 10 V to 14 Vdc power supply. Device current into Pin 14 with open output is typically 35 mA. To provide a stable reference for the ramp generator and the video output, a high quality 8.2 V regulator can supply up to 10 mA for external uses,

with an effective source impedance of less than  $1.0\ \Omega$ . This regulator is convenient for a tracking dc reference for dc coupling the output to an RF modulator. Typical turn-on drift for the regulator is approximately  $-30$  mV over 1 to 2 minutes in otherwise stable ambient conditions.

**Figure 15. Output Termination****SUMMARY**

The preceding information was intended to detail the application and basis of circuit choices for the MC1377. A complete MC1377 application with the MC1374 VHF modulator is illustrated in Figure 17. The internal schematic diagram of the MC1377 is provided in Figure 8.

**Figure 16. Application with VHF Modulator**

## APPLICATIONS INFORMATION

**S-VHS**

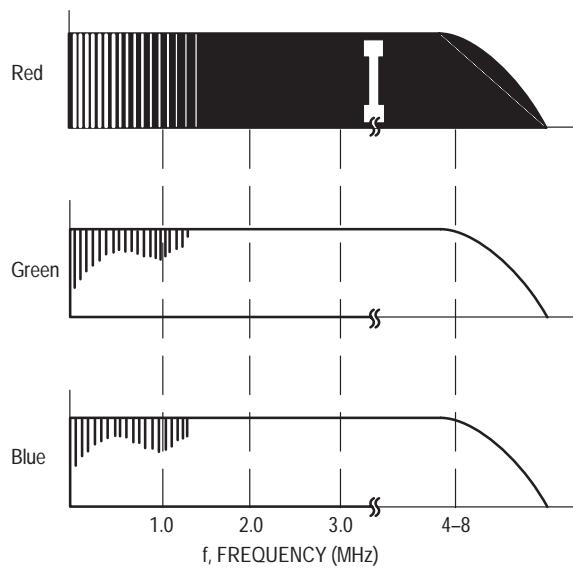
In full RGB systems (Figure 18), three information channels are provided from the signal source to the display to permit unimpaired image resolution. The detail reproduction of the system is limited only by the signal bandwidth and the capability of the color display device. Also, higher than normal sweep rates may be employed to add more lines within a vertical period and three separate projection picture tubes can be used to eliminate the "shadow mask" limitations of a conventional color CRT.

Figure 21 shows the "baseband" components of a studio NTSC signal. As in the previous example, energy is concentrated at multiples of the horizontal sweep frequency. The system is further refined by precisely locating the color subcarrier midway between luminance spectral components. This places all color spectra between luminance spectra and can be accomplished in the MC1377 only if "full interlaced" external color reference and sync are applied. The individual

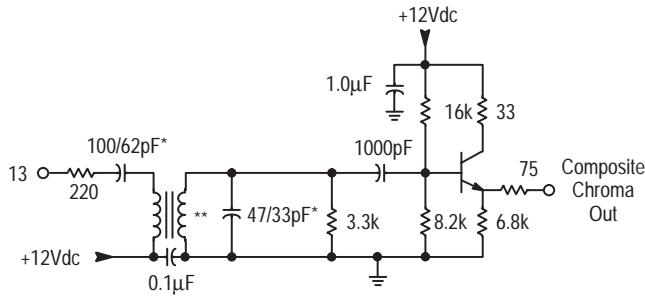
components of luminance and color can then be separated by the use of a comb filter in the monitor or receiver. This technique has not been widely used in consumer products, due to cost, but it is rapidly becoming less expensive and more common. Another technique which is gaining popularity is S-VHS (Super VHS).

In S-VHS, the chroma and luma information are contained on separate channels. This allows the bandwidth of both the chroma and luma channels to be as wide as the monitors ability to reproduce the extra high frequency information. An output coupling circuit for the composite chroma using the TOKO transformer is shown in Figure 19. It is composed of the bandpass transformer and an output buffer and has the frequency performance shown in Figure 20. The composite output (Pin 9) then produces the luma information as well as composite sync and blanking.

**Figure 17. Spectra of a Full RGB System**



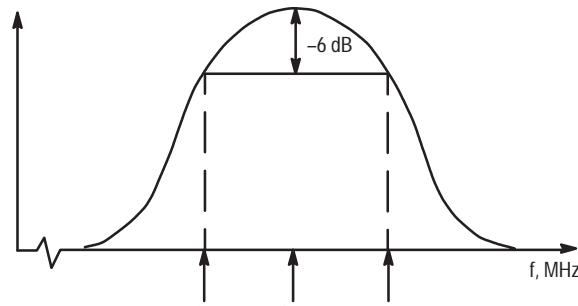
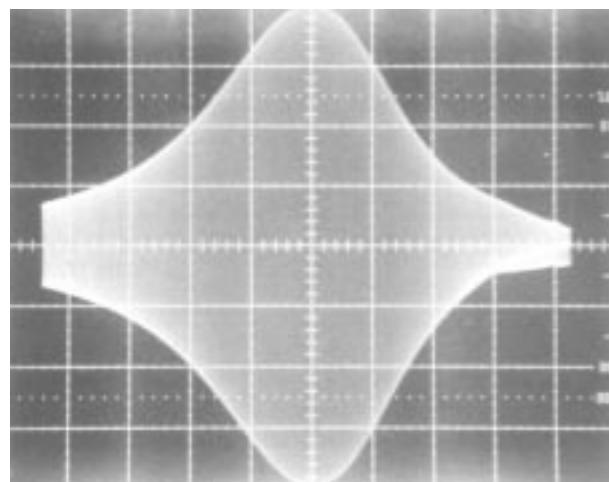
**Figure 18. S-VHS Output Buffer**



\*Refers to different component values used for NTSC/PAL (3.58 MHz/4.43 MHz).

\*\*Toko 166NNF-1026AG

**Figure 19. Frequency Response of Chroma Coupling Circuit**



### I/Q System versus (R-Y)/(B-Y) System

The NTSC standard calls for unequal bandwidths for I and Q (Figure 21). The MC1377 has no means of processing the unequal bandwidths because the I and Q axes are not used (Figure 22) and because the outputs of the (R-Y) and the (B-Y) modulators are added before being output at Pin 13. Therefore, any bandwidth reduction intended for the chroma information must be performed on the composite chroma information. This is generally not a problem, however, since most monitors compromise the standard quite a bit.

**Figure 20. NTSC Standard Spectral Content**

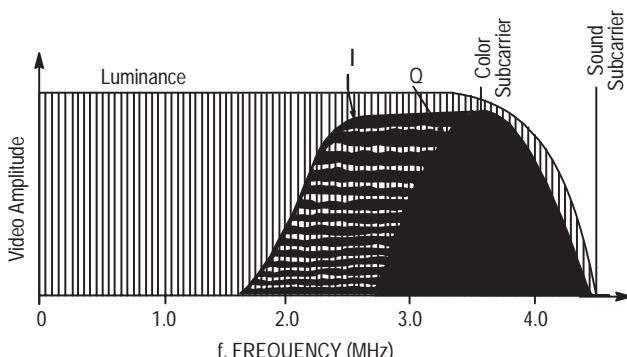
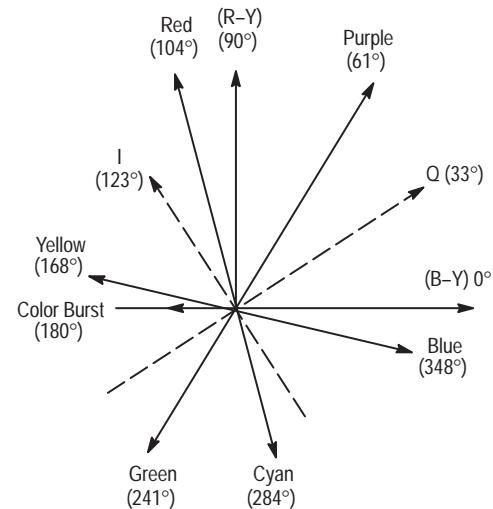
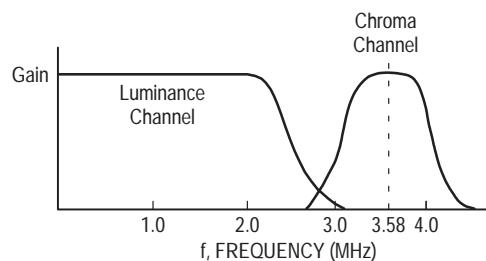


Figure 23 shows the typical response of most monitors and receivers. This figure shows that some crosstalk between luma and chroma information is always present. The acceptability of the situation is enhanced by the limited ability of the CRT to display information above 2.5 MHz. If the signal from the MC1377 is to be used primarily to drive conventional non-comb filtered monitors or receivers, it would be best to reduce the bandwidth at the MC1377 to that of Figure 23 to lessen crosstalk.

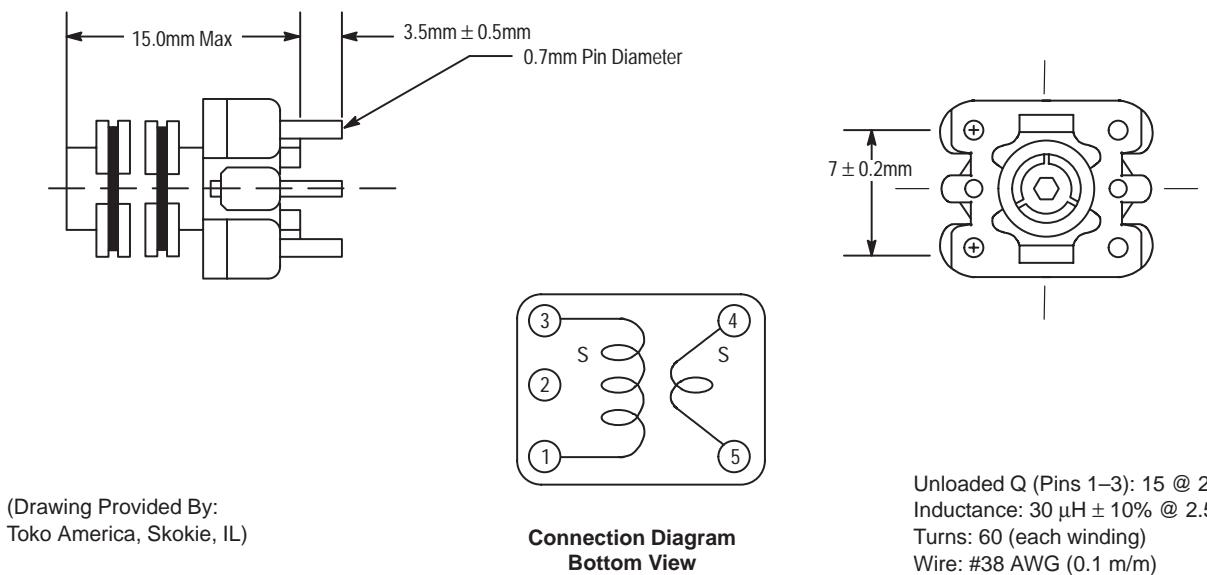
**Figure 21. Color Vector Relationship (Showing Standard Colors)**



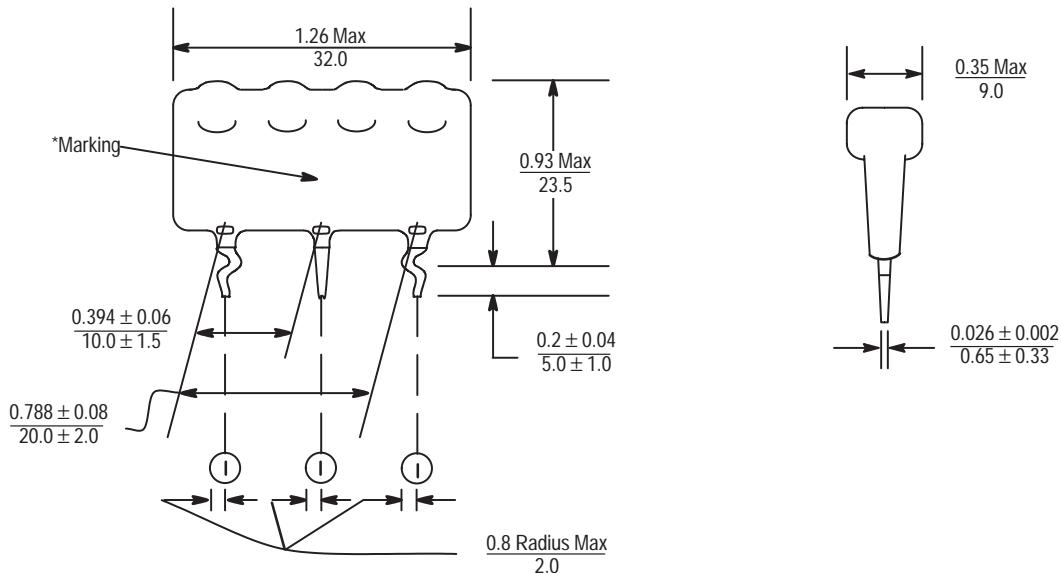
**Figure 22. Frequency Response of Typical Monitor/TV**



**Figure 23. A Prototype Chroma Bandpass Transformer**  
Toko Sample Number 166NNF-10264AG



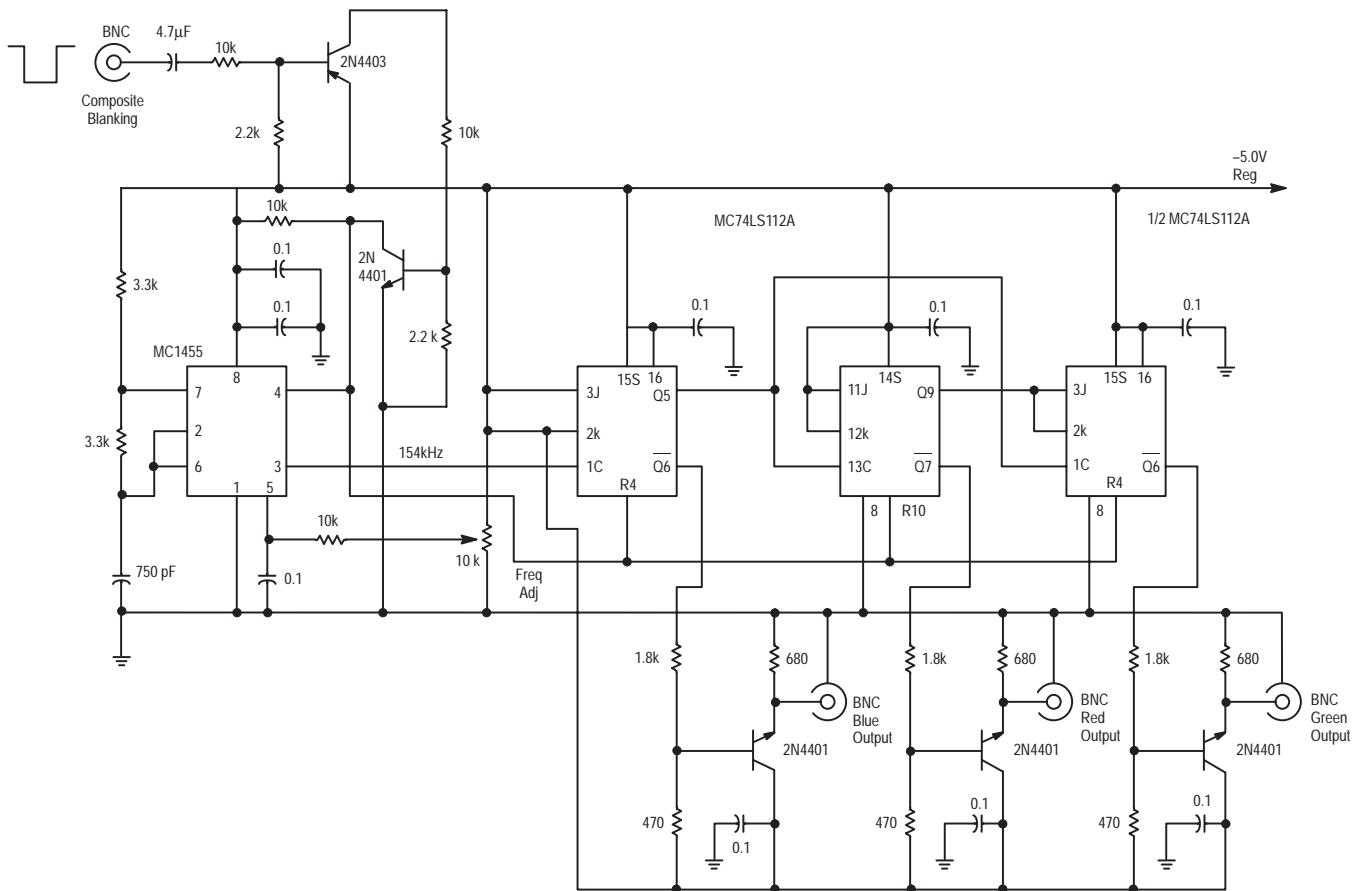
**Figure 24. A Prototype Delay Line**  
TDK Sample Number DL122301D-1533



\*Marking: Part Number, Manufacturer's Identification,  
Date Code and Lead Number.  
Skokie, IL (TDK Corporation of America)

Item	Specifications
Time Delay	$400 \text{ ns} \pm 10\%$
Impedance	$1200 \Omega \pm 10\%$
Resistance	Less Than $15 \Omega$
Transient Response with 20 ns Rise Time Input Pulse	Preshoot: 10% Max Overshoot: 10% Max Rise Time: 120 ns Max
Attenuation	3 dB Max at 6.0 MHz

Figure 25. RGB Pulse Generator



RGB Pulse Generator Timing Diagram for NTSC

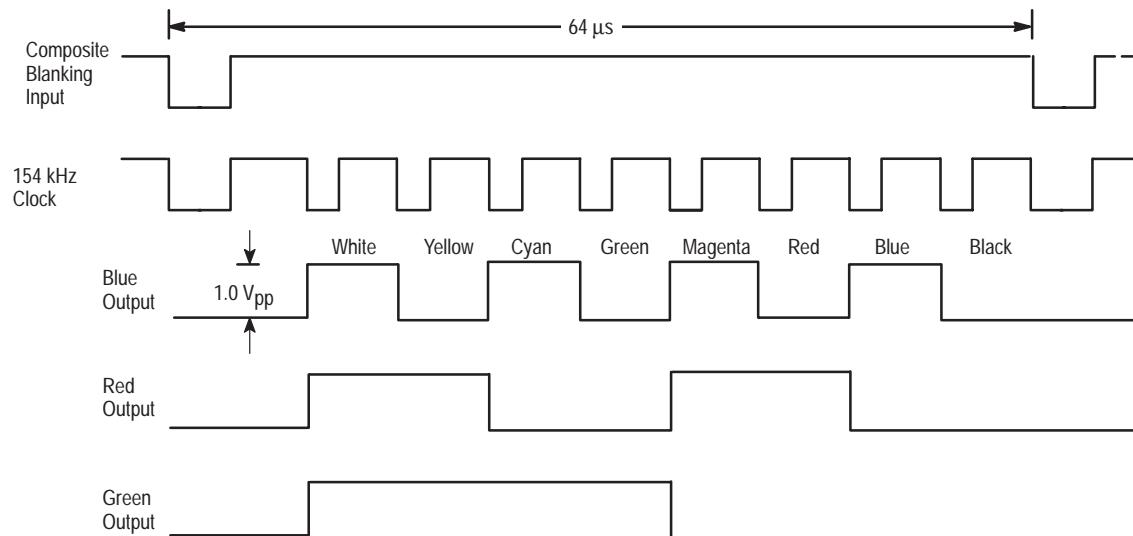
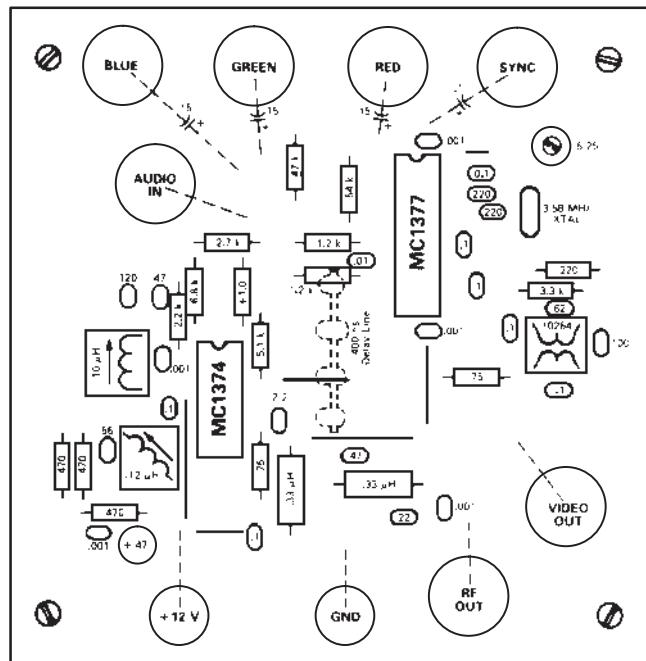


Figure 26. Printed Circuit Boards for the MC1377

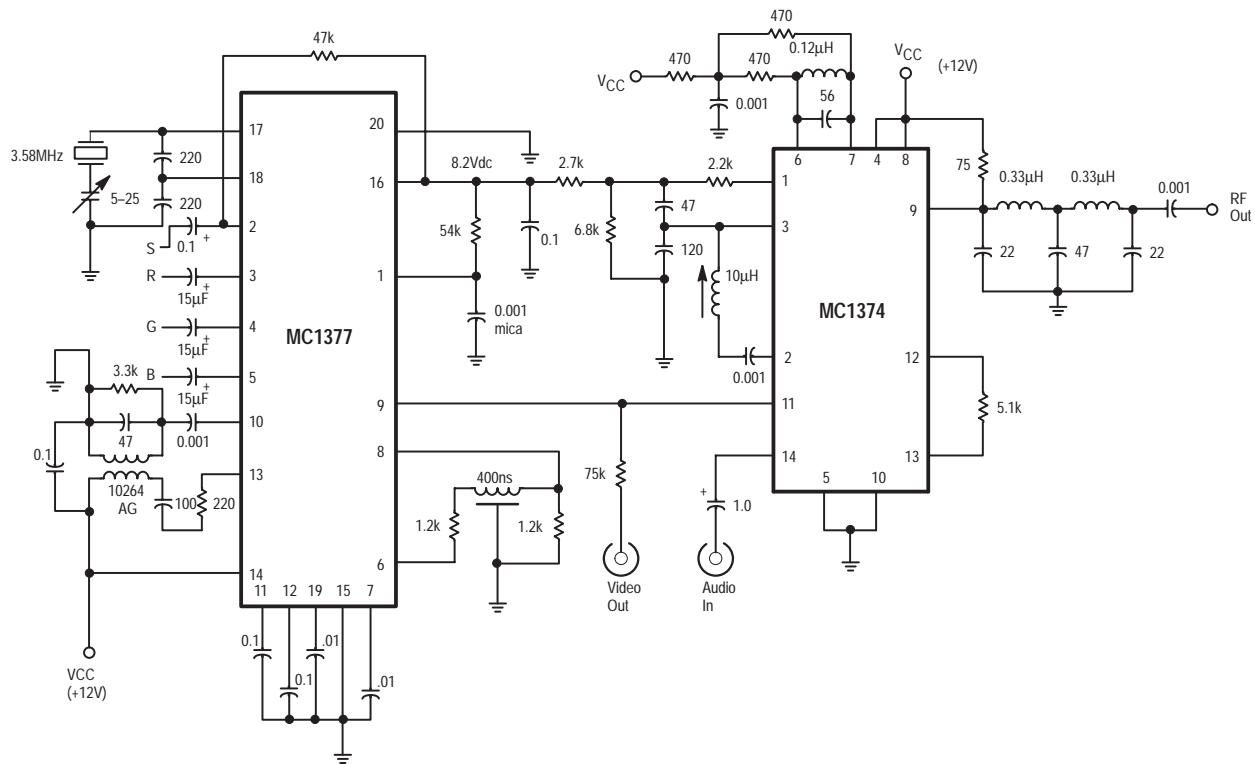


(CIRCUIT SIDE)



(COMPONENT SIZE)

Figure 27. Color TV Encoder – Modulator



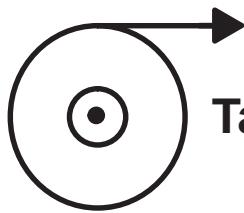
# Tape and Reel Options

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## In Brief . . .

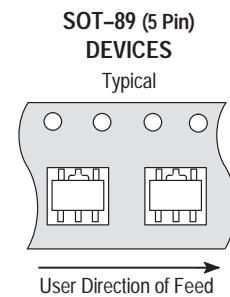
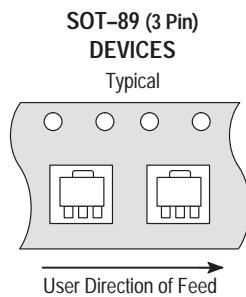
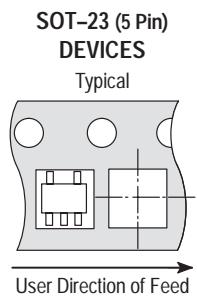
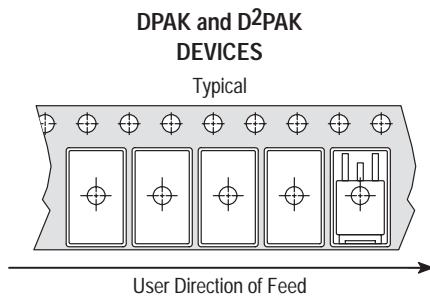
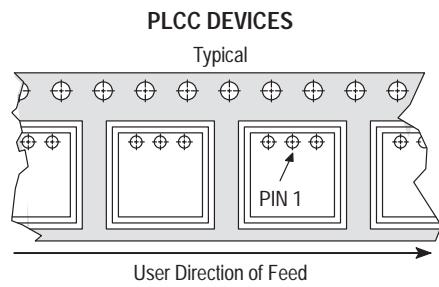
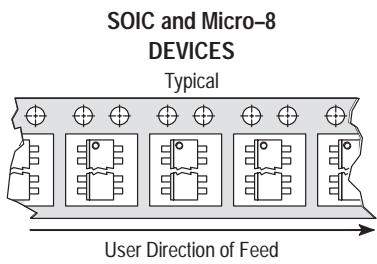
Motorola offers the convenience of Tape and Reel packaging for our growing family of standard integrated circuit products. Reels are available to support the requirements of both first and second generation pick-and-place equipment. The packaging fully conforms to the latest EIA-481A specification. The antistatic embossed tape provides a secure cavity, sealed with a peel-back cover tape.

	Page
Tape and Reel Configurations .....	12-2
Tape and Reel Information Table .....	12-4
Analog MPQ Table .....	12-5



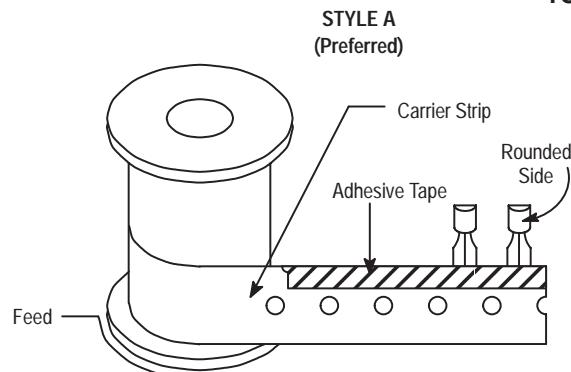
# Tape and Reel Configurations

## Mechanical Polarization

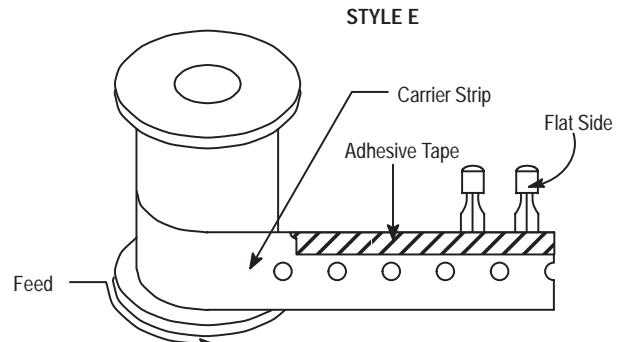


## Tape and Reel Configurations (continued)

### TO-92 Reel Styles

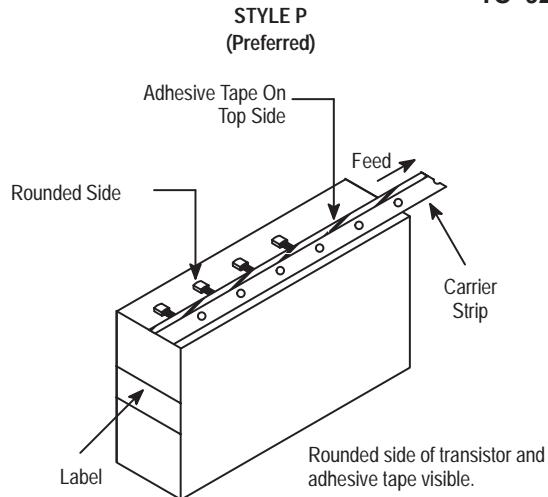


Rounded side of transistor and adhesive tape visible.

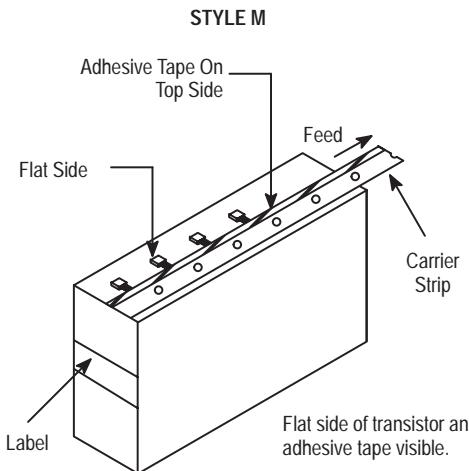


Flat side of transistor and adhesive tape visible.

### TO-92 Ammo Pack Styles

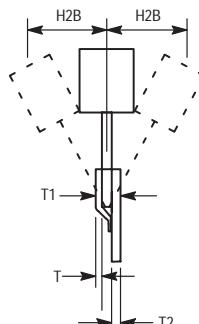
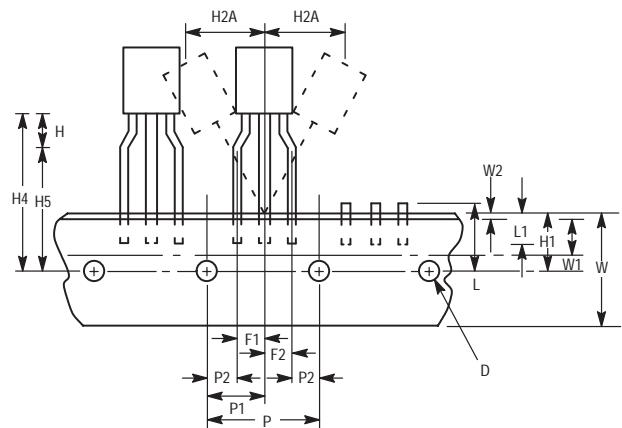


Style P ammo pack is equivalent to Styles A and B of reel pack dependent on feed orientation from box.



Style M ammo pack is equivalent to Style E of reel pack dependent on feed orientation from box.

### TO-92 EIA Radial Tape in Fan Fold Box or On Reel



# Tape and Reel Information Table

Package	Tape Width (mm)	Devices <sup>(1)</sup> per Reel	Reel Size (inch)	Device Suffix
SO-8, SOP-8	12	2,500	13	R2
SO-14	16	2,500	13	R2
SO-16	16	2,500	13	R2
SO-16L, SO-8+8L WIDE	16	1,000	13	R2
SO-20L WIDE	24	1,000	13	R2
SO-24L WIDE	24	1,000	13	R2
SO-28L WIDE	24	1,000	13	R2
SO-28L WIDE	32	1,000	13	R3
Micro-8	12	2,500	13	R2
PLCC-20	16	1,000	13	R2
PLCC-28	24	500	13	R2
PLCC-44	32	500	13	R2
PLCC-52	32	500	13	R2
PLCC-68	44	250	13	R2
PLCC-84	44	250	13	R2
TO-226AA (TO-92) <sup>(2)</sup>	18	2,000	13	RA, RE, RP, or RM (Ammo Pack) only
DPAK	16	2,500	13	RK
D <sup>2</sup> PAK	24	800	13	R4
SOT-23 (5 Pin)	8	3,000	7	TR
SOT-89 (3/5 Pin)	12	1,000	7	T1

(1) Minimum order quantity is 1 reel. Distributors/OEM customers may break lots or reels at their option, however broken reels may not be returned.

(2) Integrated circuits in TO-226AA packages are available in Styles A and E only, with optional "Ammo Pack" (Suffix RP or RM). The RA and RP configurations are preferred. For ordering information please contact your local Motorola Semiconductor Sales Office.

# Analog MPQ Table

## Tape/Reel and Ammo Pack

Package Type	Package Code	MPQ
<b>PLCC</b>		
Case 775	0802	1000/reel
Case 776	0804	500/reel
Case 777	0801	500/reel
<b>SOIC</b>		
Case 751	0095	2500/reel
Case 751A	0096	2500/reel
Case 751B	0097	2500/reel
Case 751G	2003	1000/reel
Case 751D	2005	1000/reel
Case 751E	2008	1000/reel
Case 751F	2009	1000/reel
<b>Micro-8</b>		
Case 846A	-	2500/reel
<b>TO-92</b>		
Case 29	0031	2000/reel
Case 29	0031	2000/Ammo Pack
<b>DPAK</b>		
Case 369A	-	2500/reel
<b>D<sup>2</sup>PAK</b>		
Case 936	-	800/reel
<b>SOT-23 (5 Pin)</b>		
Case 1212	-	3000/reel
<b>SOT-89 (3 Pin)</b>		
Case 1213	-	1000/reel
<b>SOT-89 (5 Pin)</b>		
Case 1214	-	1000/reel



# Packaging Information

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## In Brief . . .

The packaging availability for each device type is indicated on the individual data sheets and the Selector Guide. All of the outline dimensions for the packages are given in this section.

The maximum power consumption an integrated circuit can tolerate at a given operating ambient temperature can be found from the equation:

$$P_{D(TA)} = \frac{T_{J(max)} - T_A}{R_{\theta JA}(\text{Typ})}$$

where:

$P_{D(TA)}$  = Power Dissipation allowable at a given operating ambient temperature. This must be greater than the sum of the products of the supply voltages and supply currents at the worst case operating condition.

$T_{J(max)}$  = Maximum operating Junction Temperature as listed in the Maximum Ratings Section. See individual data sheets for  $T_{J(max)}$  information.

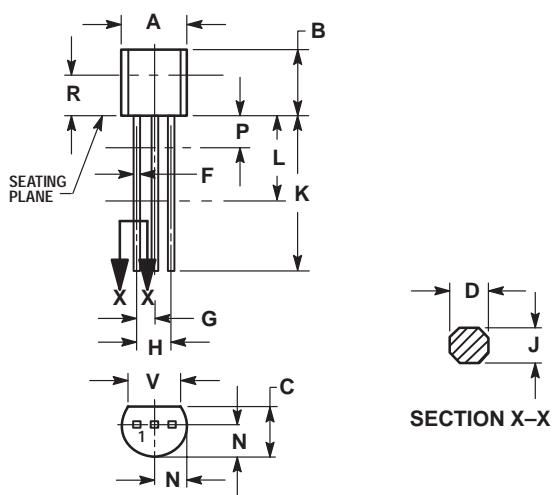
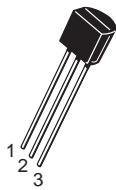
$T_A$  = Maximum desired operating Ambient Temperature

$R_{\theta JA}(\text{Typ})$  = Typical Thermal Resistance Junction-to-Ambient

# Case Outline Dimensions

**LP, P, Z SUFFIX  
CASE 29-04**

Plastic Package  
(TO-226AA/TO-92)  
ISSUE AD



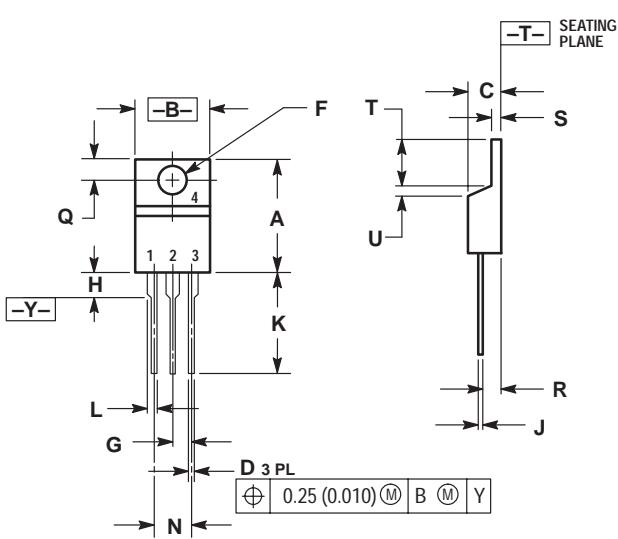
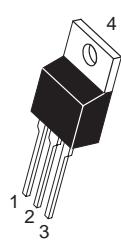
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. DIMENSION F APPLIES BETWEEN P AND L. DIMENSION D AND J APPLY BETWEEN L AND K MINIMUM. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.022	0.41	0.55
F	0.016	0.019	0.41	0.48
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	—	12.70	—
L	0.250	—	6.35	—
N	0.080	0.105	2.04	2.66
P	—	0.100	—	2.54
R	0.115	—	2.93	—
V	0.135	—	3.43	—

**KC, T SUFFIX  
CASE 221A-06**

Plastic Package  
ISSUE Y

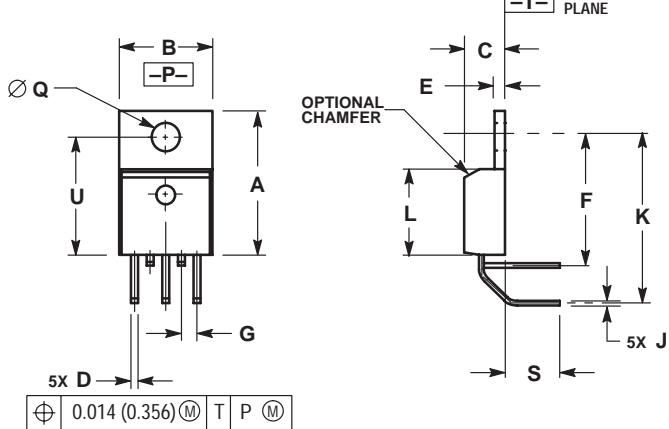
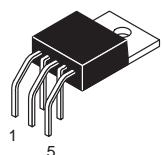


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.560	0.625	14.23	15.87
B	0.380	0.420	9.66	10.66
C	0.140	0.190	3.56	4.82
D	0.020	0.045	0.51	1.14
F	0.139	0.155	3.53	3.93
G	0.100 BSC	—	2.54 BSC	—
H	—	0.280	—	7.11
J	0.012	0.045	0.31	1.14
K	0.500	0.580	12.70	14.73
L	0.045	0.070	1.15	1.77
N	0.200 BSC	—	5.08 BSC	—
Q	0.100	0.135	2.54	3.42
R	0.080	0.115	2.04	2.92
S	0.020	0.055	0.51	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27

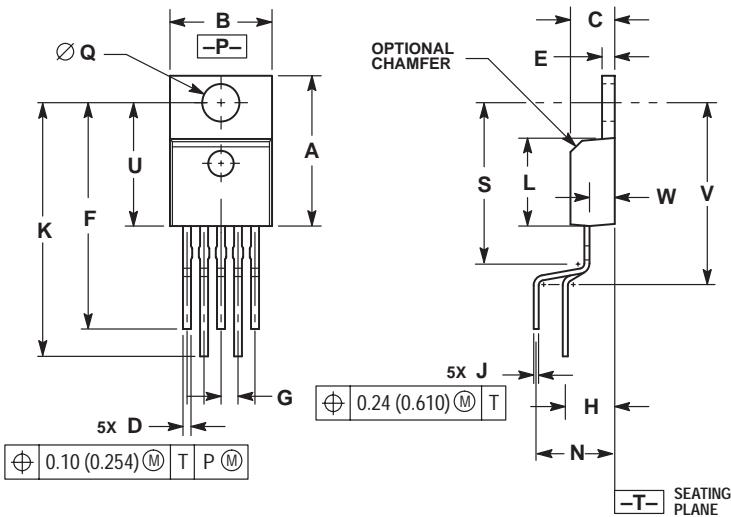
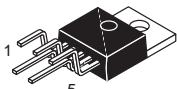
**TH SUFFIX**  
**CASE 314A-03**  
 Plastic Package  
 ISSUE D



NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
 2. CONTROLLING DIMENSION: INCH.  
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 0.043 (1.092) MAXIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
F	0.570	0.585	14.478	14.859
G	0.067 BSC		1.702 BSC	
J	0.015	0.025	0.381	0.635
K	0.730	0.745	18.542	18.923
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
S	0.210	0.260	5.334	6.604
U	0.468	0.505	11.888	12.827

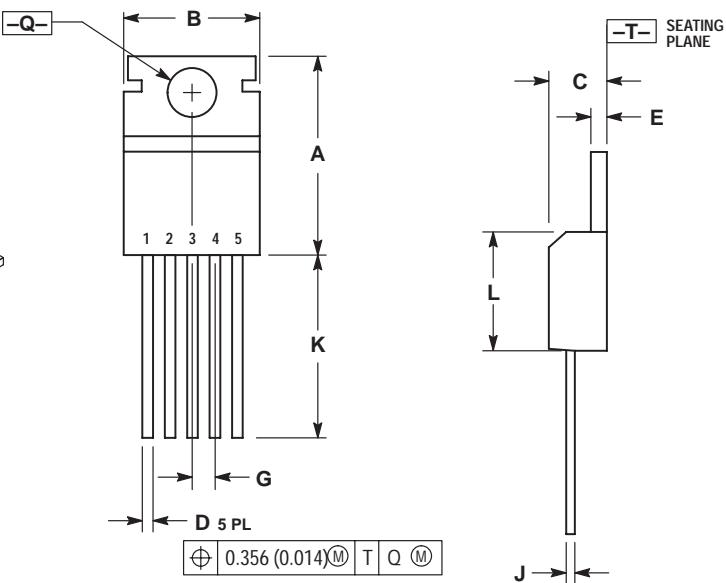
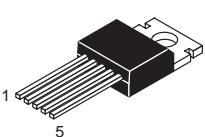
**T, TV SUFFIX**  
**CASE 314B-05**  
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 ISSUE J



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 2. CONTROLLING DIMENSION: INCH.  
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 0.043 (1.092) MAXIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
F	0.850	0.935	21.590	23.749
G	0.067 BSC		1.702 BSC	
H	0.166 BSC		4.216 BSC	
J	0.015	0.025	0.381	0.635
K	0.900	1.100	22.860	27.940
L	0.320	0.365	8.128	9.271
N	0.320 BSC		8.128 BSC	
Q	0.140	0.153	3.556	3.886
S	—	0.620	—	15.748
U	0.468	0.505	11.888	12.827
V	—	0.735	—	18.669
W	0.090	0.110	2.286	2.794

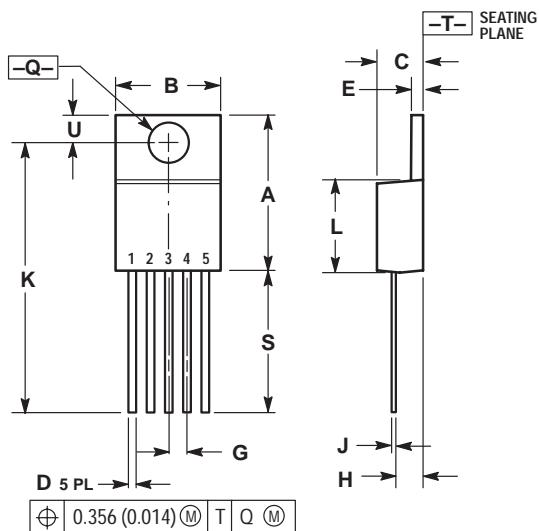
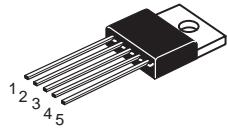
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 ISSUE A



NOTES:  
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 2. CONTROLLING DIMENSION: INCH.  
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.610	0.625	15.59	15.88
B	0.380	0.420	9.65	10.67
C	0.160	0.190	4.06	4.83
D	0.020	0.040	0.51	1.02
E	0.035	0.055	0.89	1.40
G	0.067 BSC		1.702 BSC	
J	0.015	0.025	0.38	0.64
K	0.500	—	12.70	—
L	0.355	0.370	9.02	9.40
Q	0.139	0.147	3.53	3.73

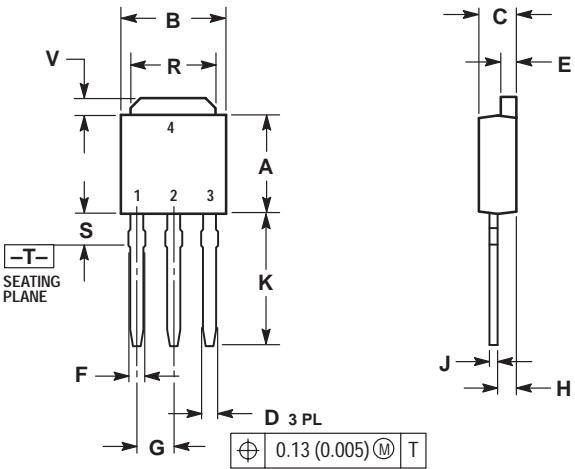
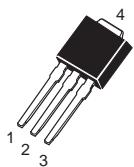
**T, T1 SUFFIX  
CASE 314D-03**  
Plastic Package  
ISSUE D



NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
 2. CONTROLLING DIMENSION: INCH.  
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
G	0.067 BSC		1.702 BSC	
H	0.087	0.112	2.210	2.845
J	0.015	0.025	0.381	0.635
K	1.020	1.065	25.908	27.051
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
U	0.105	0.117	2.667	2.972
S	0.543	0.582	13.792	14.783

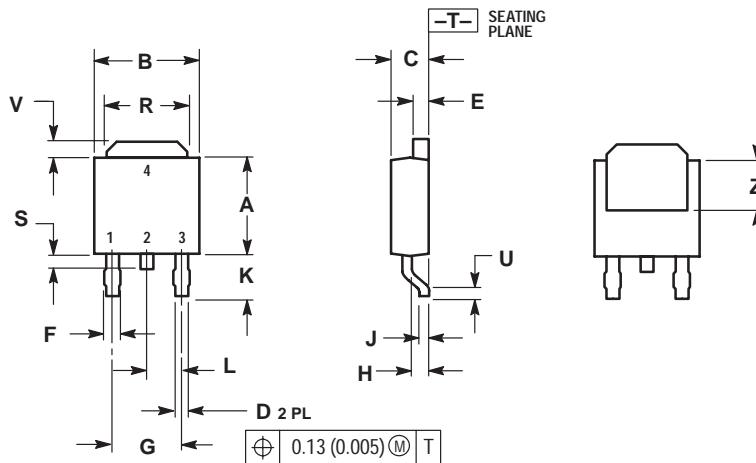
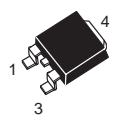
**DT-1 SUFFIX  
CASE 369-07**  
Plastic Package  
(DPAK)  
ISSUE K



NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.175	0.215	4.45	5.46
S	0.050	0.090	1.27	2.28
V	0.030	0.050	0.77	1.27

**DT SUFFIX  
CASE 369A-13**  
Plastic Package  
(DPAK)  
ISSUE Y



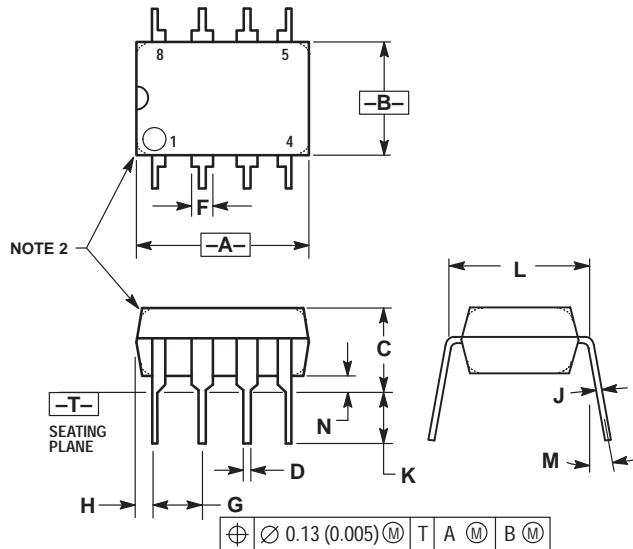
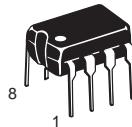
NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.180 BSC		4.58 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.175	0.215	4.45	5.46
S	0.020	0.050	0.51	1.27
U	0.020	---	0.51	---
V	0.030	0.050	0.77	1.27
Z	0.138	---	3.51	---

**DP1, N, P, P1 SUFFIX****CASE 626-05**

Plastic Package

ISSUE K



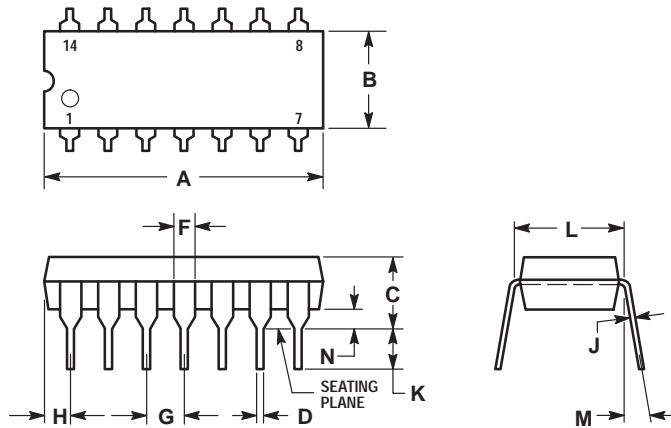
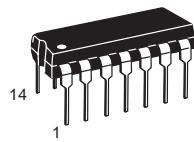
## NOTES:

1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
2. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

**N, P, N-14, P2 SUFFIX****CASE 646-06**

Plastic Package

ISSUE L



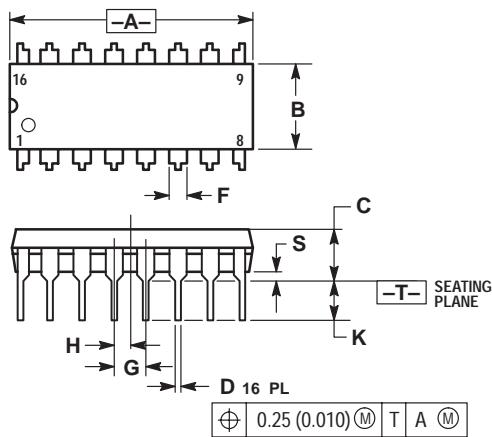
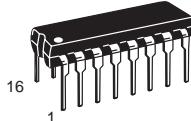
## NOTES:

1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
4. ROUNDED CORNERS OPTIONAL.

**DP2, N, P, PC SUFFIX****CASE 648-08**

Plastic Package

ISSUE R



## NOTES:

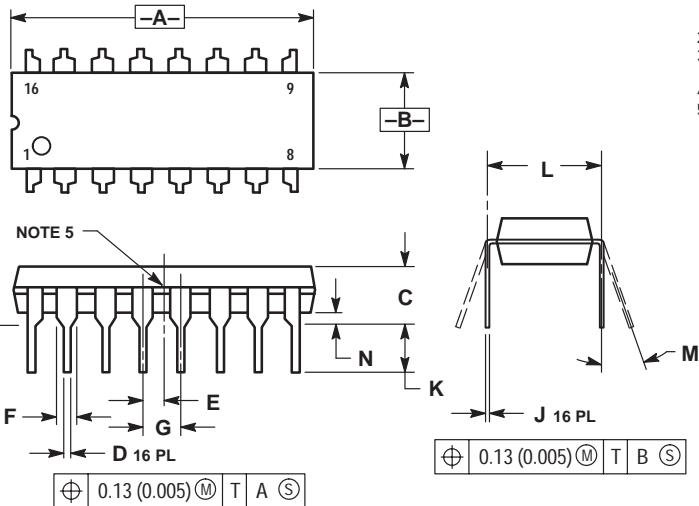
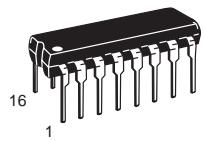
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

**B, P, P2, V SUFFIX****CASE 648C-03**

Plastic Package

(DIP-16)

ISSUE C



## NOTES:

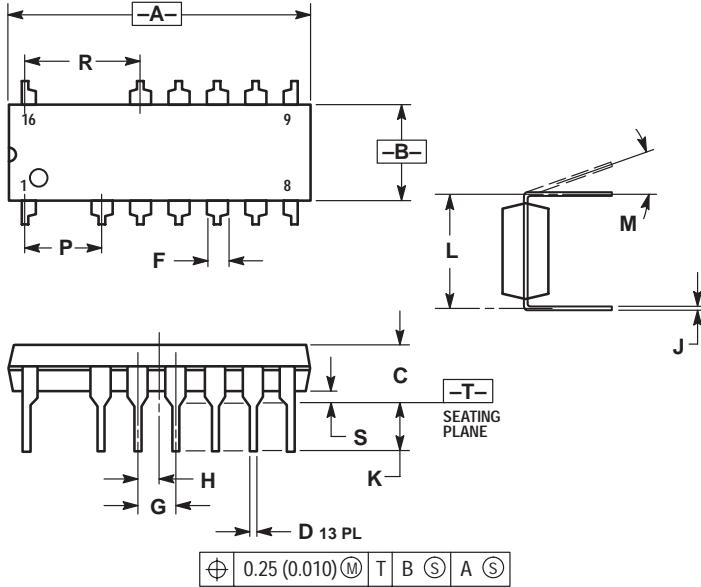
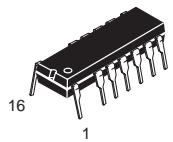
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. INTERNAL LEAD CONNECTION BETWEEN 4 AND 5, 12 AND 13.

**P SUFFIX****CASE 648E-01**

Plastic Package

(DIP-16)

ISSUE O



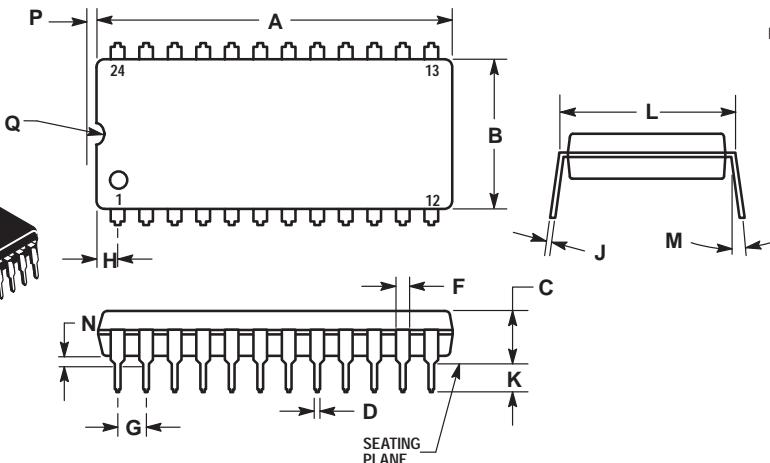
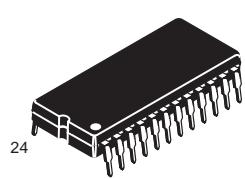
## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION A AND B DOES NOT INCLUDE MOLD PROTRUSION.
5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.25 (0.010).
6. ROUNDED CORNER OPTIONAL.

**P SUFFIX****CASE 649-03**

Plastic Package

ISSUE D



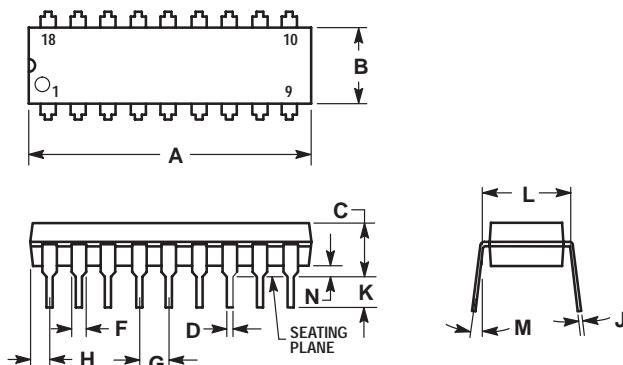
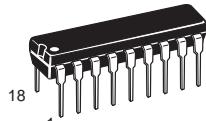
## NOTES:

1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

**A, B, N, P SUFFIX****CASE 707-02**

Plastic Package

ISSUE C



## NOTES:

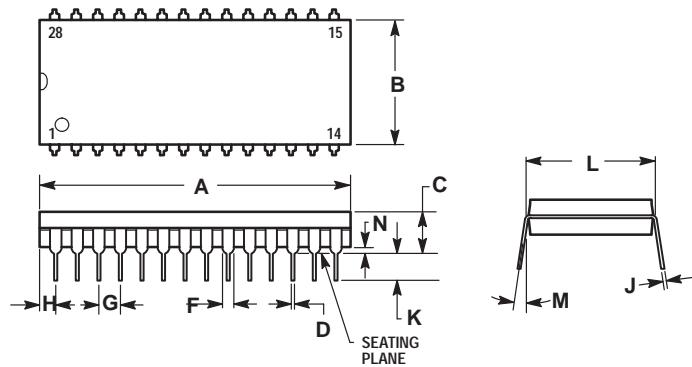
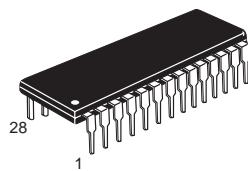
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.22	23.24	0.875	0.915
B	6.10	6.60	0.240	0.260
C	3.56	4.57	0.140	0.180
D	0.36	0.56	0.014	0.022
F	1.27	1.78	0.050	0.070
G	2.54 BSC		0.100 BSC	
H	1.02	1.52	0.040	0.060
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

**P SUFFIX****CASE 710-02**

Plastic Package

ISSUE B



## NOTES:

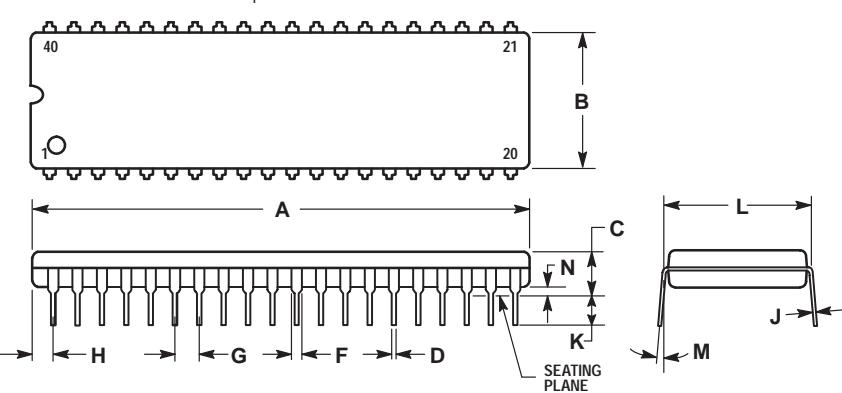
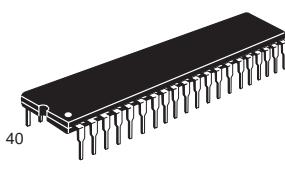
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	36.45	37.21	1.435	1.465
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

**P SUFFIX****CASE 711-03**

Plastic Package

ISSUE C



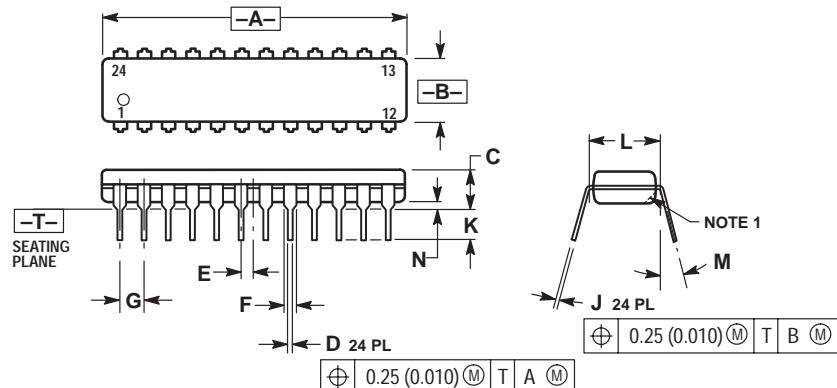
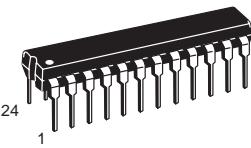
## NOTES:

1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

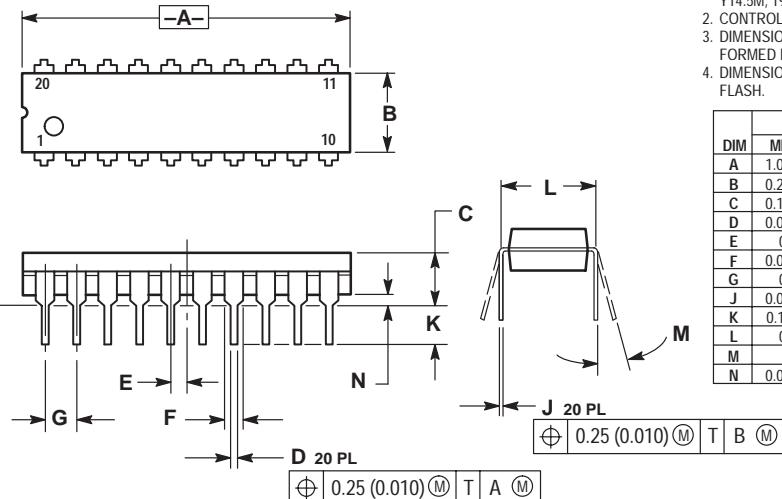
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	51.69	52.45	2.035	2.065
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

**F, P, P-3 SUFFIX****CASE 724-03**

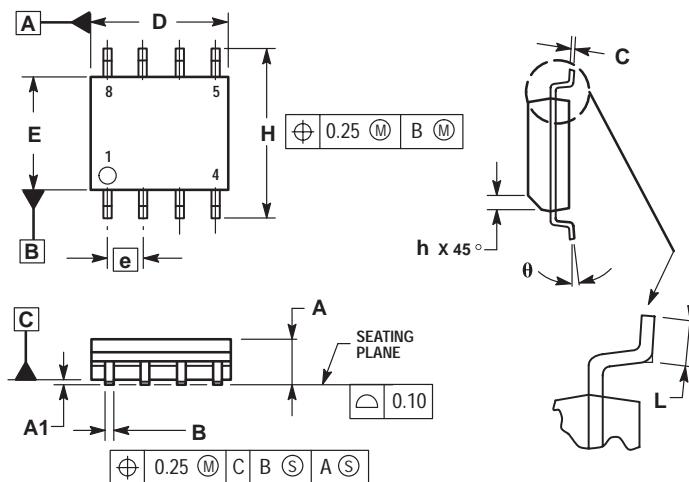
Plastic Package  
(NDIP-24)  
ISSUE D

**H, P, DP SUFFIX****CASE 738-03**

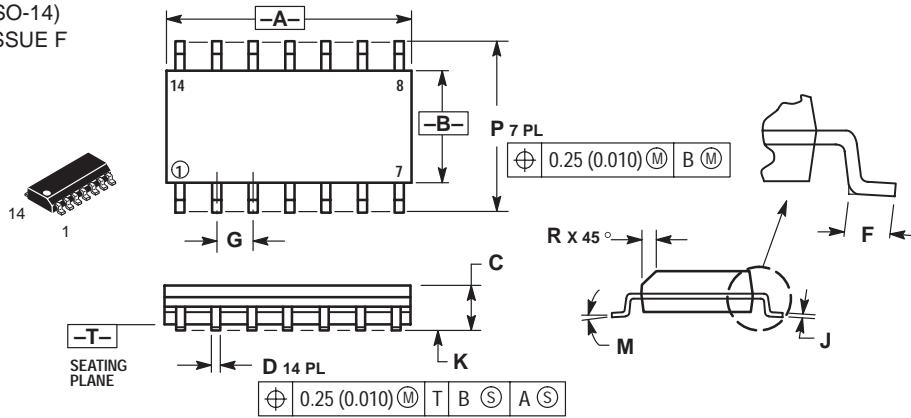
Plastic Package  
ISSUE E

**D, D1, D2 SUFFIX****CASE 751-05**

Plastic Package  
(SO-8, SOP-8)  
ISSUE R



**D SUFFIX**  
**CASE 751A-03**  
 Plastic Package  
 (SO-14)  
 ISSUE F

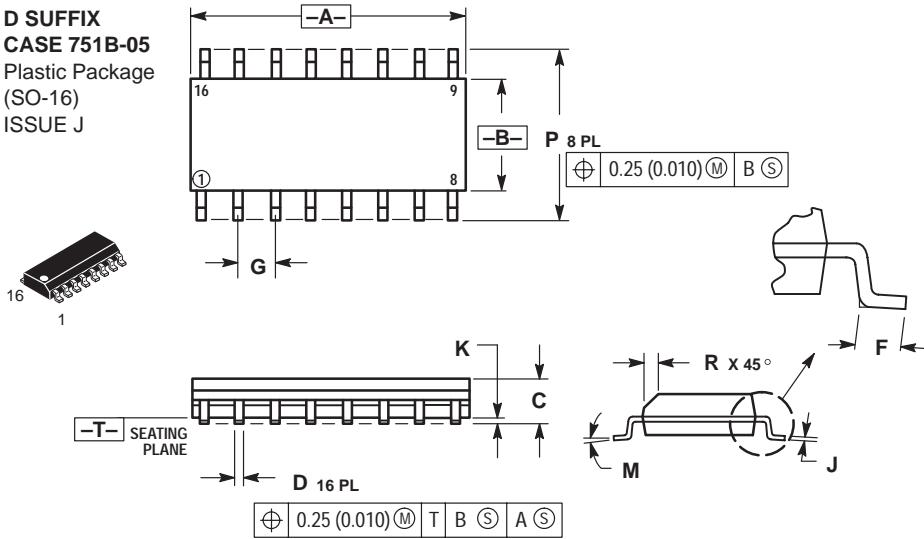


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

**D SUFFIX**  
**CASE 751B-05**  
 Plastic Package  
 (SO-16)  
 ISSUE J

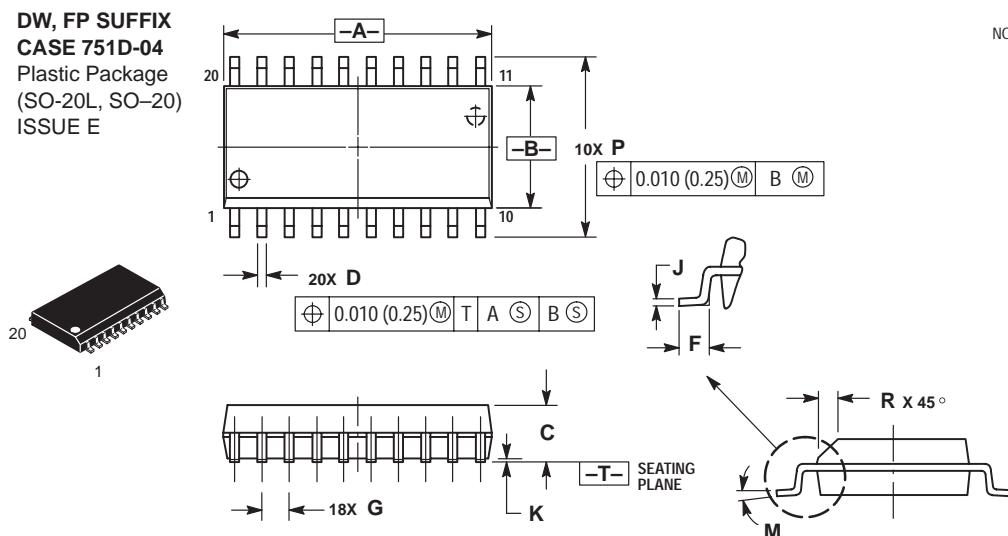


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

**DW, FP SUFFIX**  
**CASE 751D-04**  
 Plastic Package  
 (SO-20L, SO-20)  
 ISSUE E

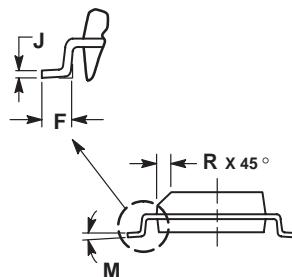
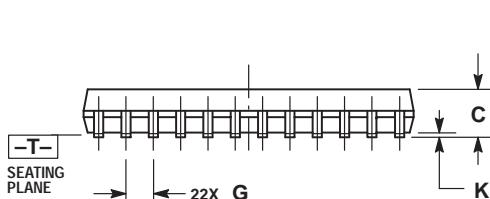
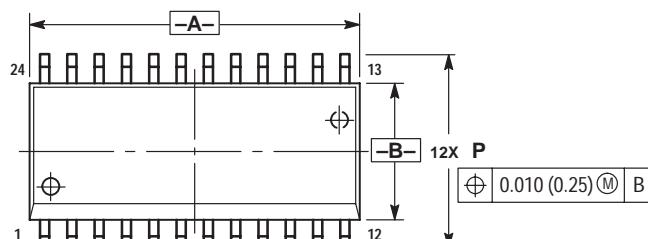
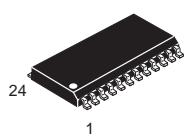


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.65	12.95	0.499	0.510
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

**DW SUFFIX**  
**CASE 751E-04**  
 Plastic Package  
 (SO-24L,  
 SOP (16+4+4)L)  
 ISSUE E

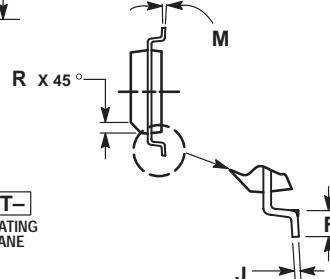
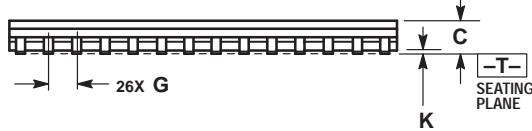
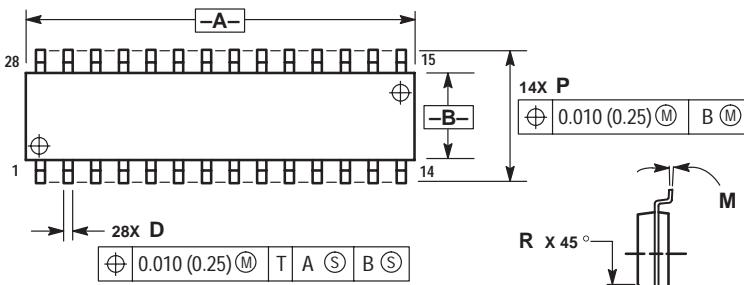
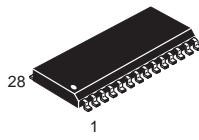


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	15.25	15.54	0.601	0.612
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0°	8°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

**DW SUFFIX**  
**CASE 751F-04**  
 Plastic Package  
 (SO-28L, SOIC-28)  
 ISSUE E

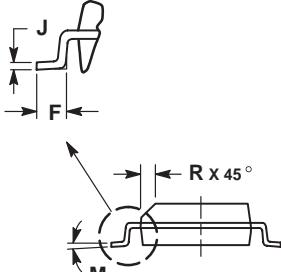
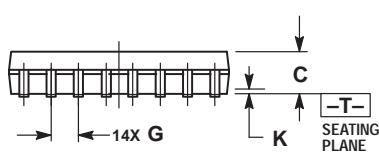
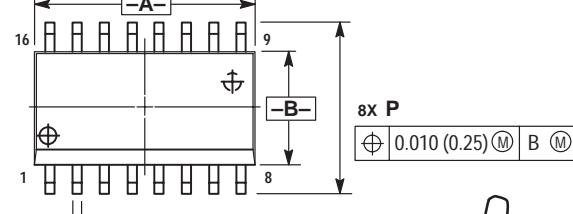
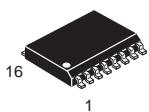


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	17.80	18.05	0.701	0.711
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0°	8°
P	10.01	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

**DW SUFFIX**  
**CASE 751G-02**  
 Plastic Package  
 (SO-16L, SOP-16L,  
 SOP-8+8L)  
 ISSUE A



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

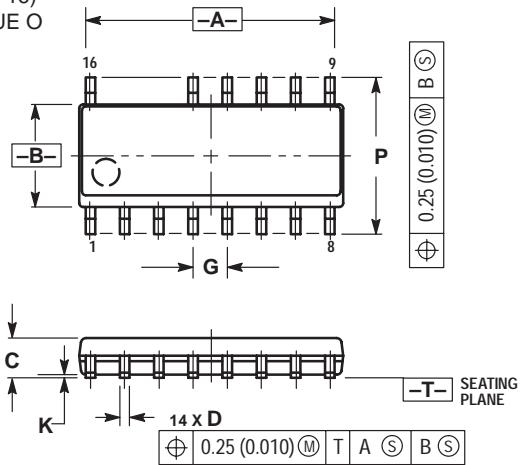
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

**D SUFFIX****CASE 751K-01**

Plastic Package

(SO-16)

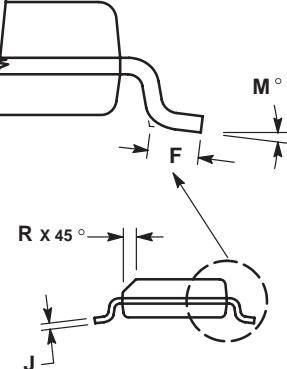
ISSUE O



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

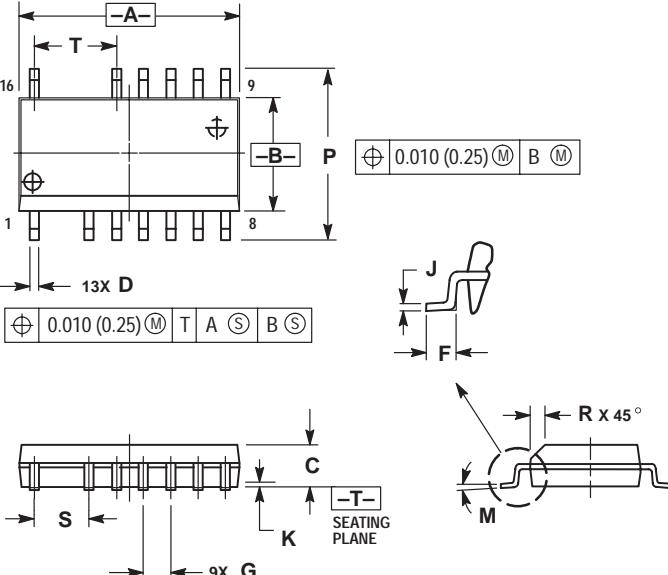
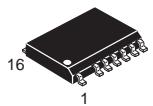
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.388	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

**DW SUFFIX****CASE 751N-01**

Plastic Package

(SOP-16L)

ISSUE O

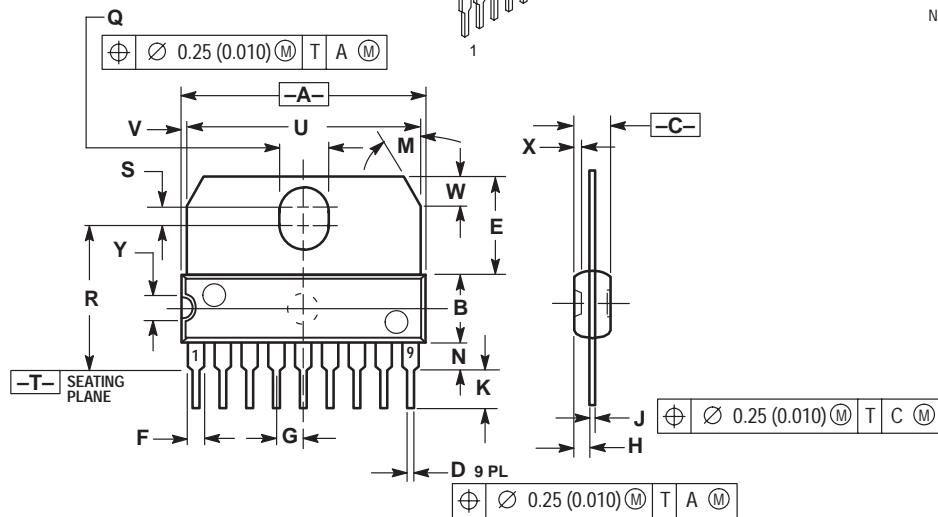
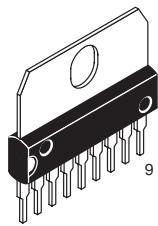


## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029
S	2.54 BSC		0.100 BSC	
T	3.81 BSC		0.150 BSC	

**CASE 762-01**

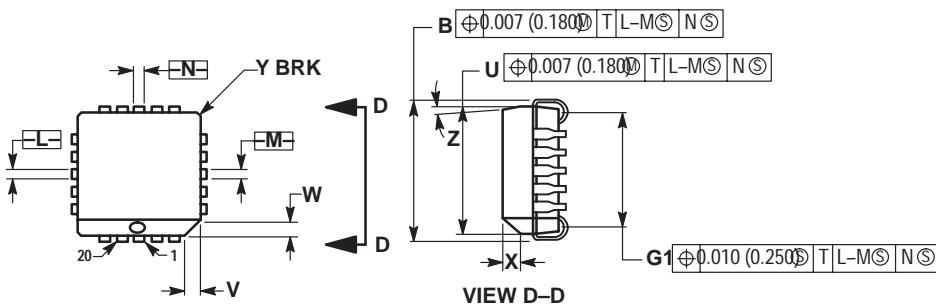
 Plastic Medium Power Package  
 (SIP-9)  
 ISSUE C


## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.

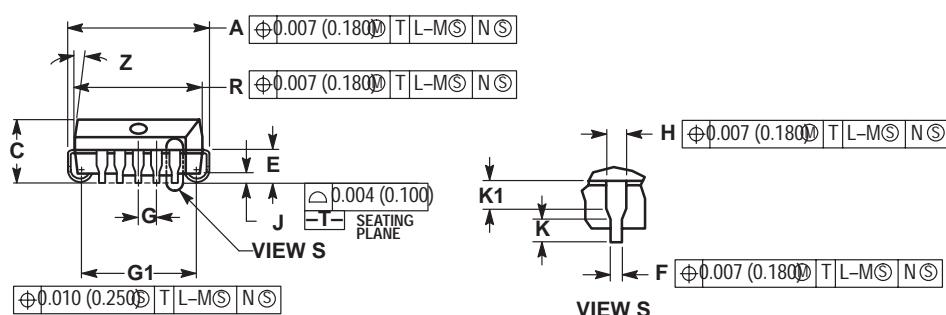
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.40	23.00	0.873	0.897
B	6.40	6.60	0.252	0.260
C	3.45	3.65	0.135	0.143
D	0.40	0.55	0.015	0.021
E	9.35	9.60	0.368	0.377
F	1.40	1.60	0.055	0.062
G	2.54 BSC		0.100 BSC	
H	1.51	1.71	0.059	0.067
J	0.360	0.400	0.014	0.015
K	3.95	4.20	0.155	0.165
M	30 °BSC		30 °BSC	
N	2.50	2.70	0.099	0.106
Q	3.15	3.45	0.124	0.135
R	13.60	13.90	0.535	0.547
S	1.65	1.95	0.064	0.076
U	22.00	22.20	0.866	0.874
V	0.55	0.75	0.021	0.029
W	2.89 BSC		0.113 BSC	
X	0.65	0.75	0.025	0.029
Y	2.70	2.80	0.106	0.110

**FN SUFFIX**
**CASE 775-02**

 Plastic Package  
 (PLCC-20)  
 ISSUE C


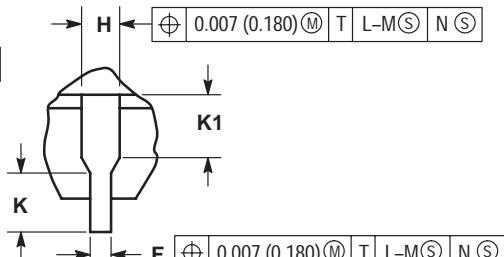
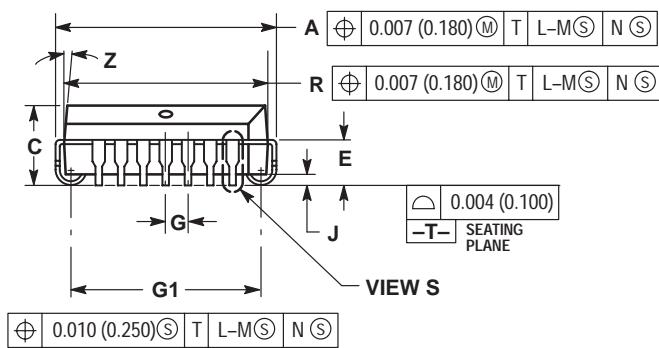
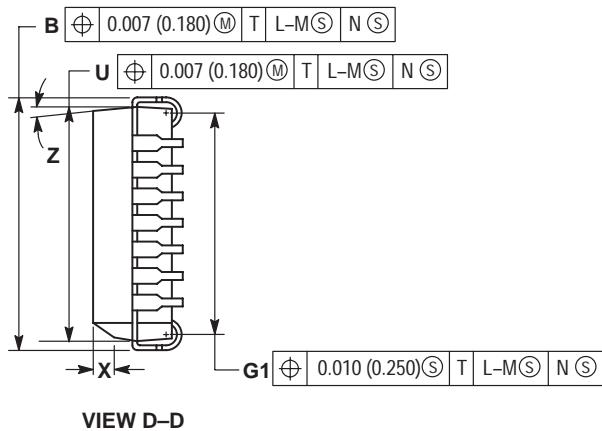
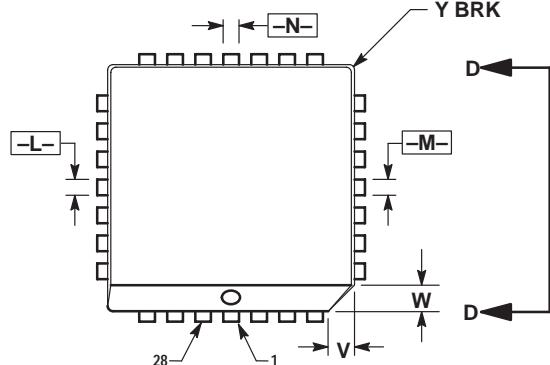
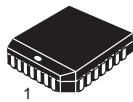
## NOTES:

1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2 °	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040	—	1.02	—

**FN SUFFIX**  
**CASE 776-02**  
Plastic Package  
(PLCC-28)  
ISSUE D

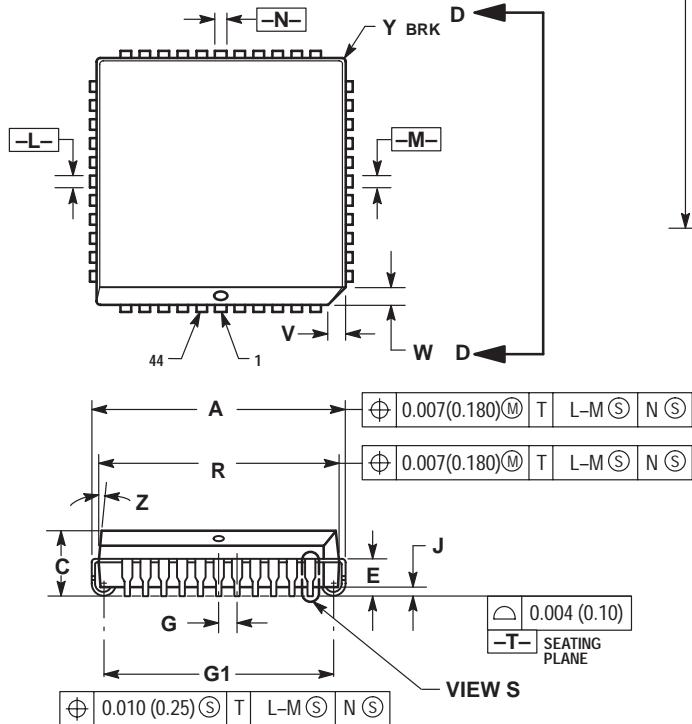
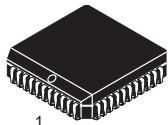


NOTES:

- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	---	1.02	---

**FN SUFFIX**  
**CASE 777-02**  
Plastic Package  
(PLCC)  
ISSUE C



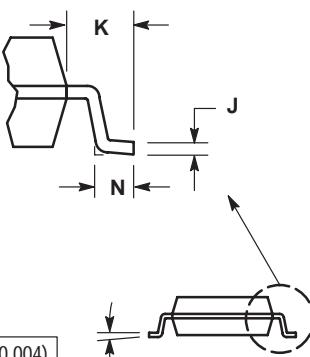
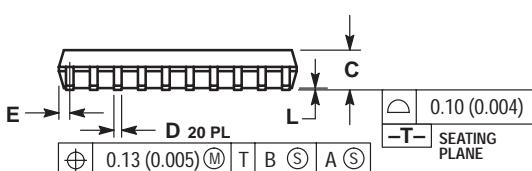
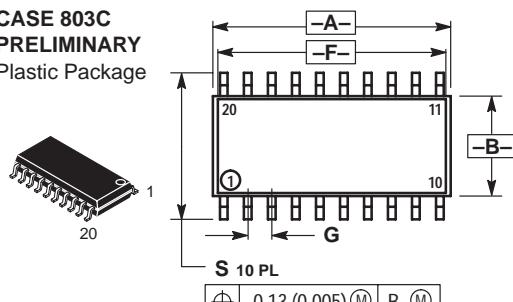
NOTES:

- DATUMS -L-, -M-, AND -N- ARE DETERMINED WHERE TOP OF LEAD SHOULDER EXISTS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.25) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.

- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.685	0.695	17.40	17.65
B	0.685	0.695	17.40	17.65
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.650	0.656	16.51	16.66
U	0.650	0.656	16.51	16.66
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2°	10°	2°	10°
G1	0.610	0.630	15.50	16.00
K1	0.040	—	1.02	—

**M SUFFIX**  
**CASE 803C**  
PRELIMINARY  
Plastic Package

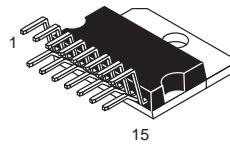


- NOTES:
- CONTROLLING DIMENSION: MILLIMETER.
  - DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  - MAXIMUM MOLD PROTRUSION 0.15 (0.008) PER SIDE.
  - DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.006) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

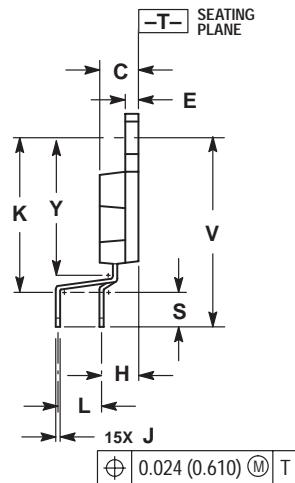
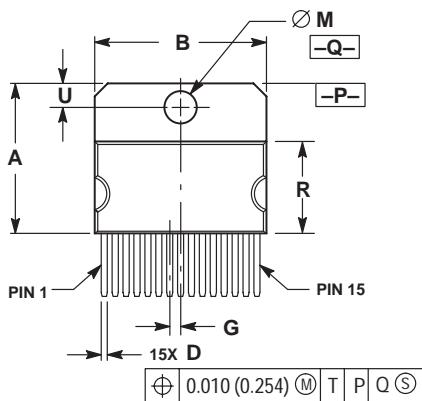
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.35	12.80	0.486	0.504
B	5.10	5.45	0.201	0.215
C	1.95	2.05	0.077	0.081
D	0.35	0.50	0.014	0.020
E	—	0.81	—	0.032
F	12.40*	—	0.488*	—
G	1.15	1.39	0.045	0.055
H	0.59	0.81	0.023	0.032
J	0.18	0.27	0.007	0.011
K	1.10	1.50	0.043	0.059
L	0.05	0.20	0.001	0.008
M	0°	10°	0°	10°
N	0.50	0.85	0.020	0.033
S	7.40	8.20	0.291	0.323

\*APPROXIMATE

**TV SUFFIX**  
**CASE 821C-04**  
 Plastic Package  
 (15-Pin ZIP)  
 ISSUE D



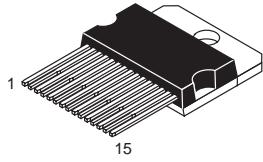
15



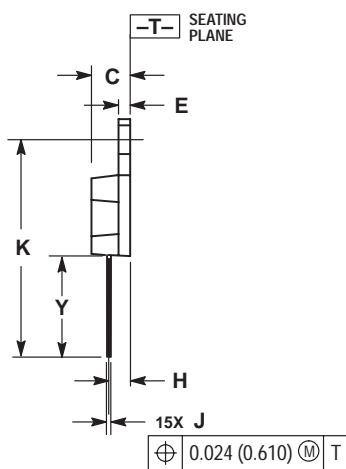
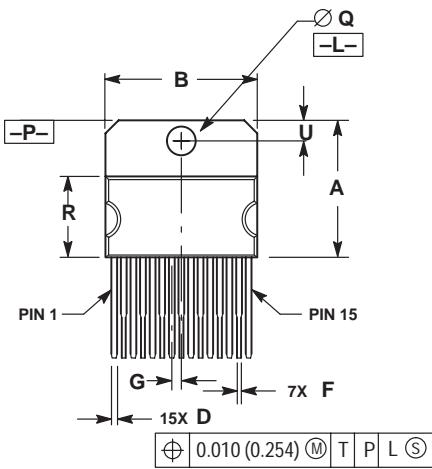
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
  5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
  6. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION. AT MAXIMUM MATERIAL CONDITION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.684	0.694	17.374	17.627
B	0.784	0.792	19.914	20.116
C	0.173	0.181	4.395	4.597
D	0.024	0.031	0.610	0.787
E	0.058	0.062	1.473	1.574
G	0.050 BSC		1.270 BSC	
H	0.169 BSC		4.293 BSC	
J	0.018	0.024	0.458	0.609
K	0.700	0.710	17.780	18.034
L	0.200 BSC		5.080 BSC	
M	0.148	0.151	3.760	3.835
R	0.416	0.426	10.567	10.820
S	0.157	0.167	3.988	4.242
U	0.105	0.115	2.667	2.921
V	0.868 REF		22.047 REF	
Y	0.625	0.639	15.875	16.231

**T SUFFIX**  
**CASE 821D-03**  
 Plastic Package  
 ISSUE C



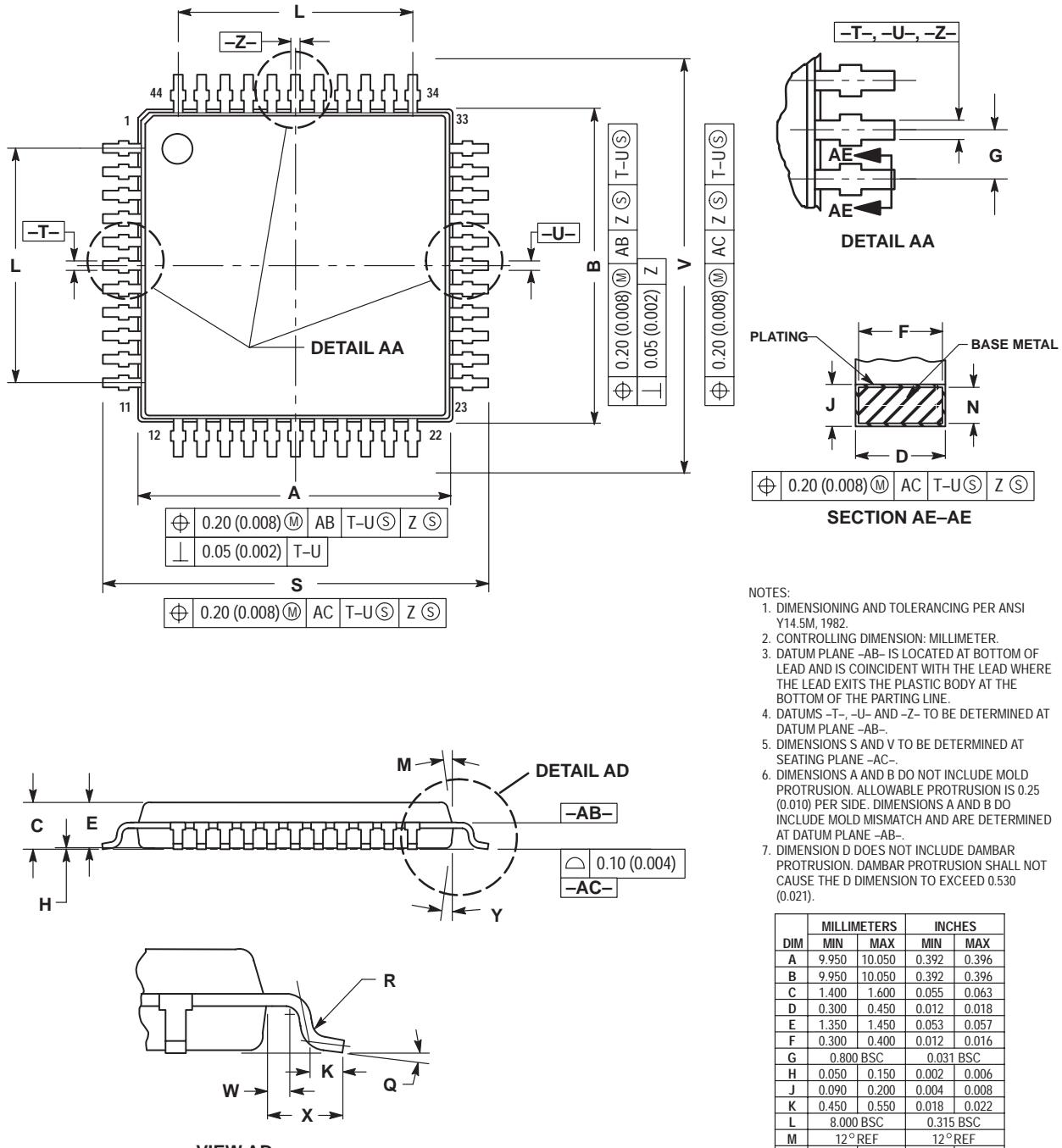
15



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
  5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
  6. DELETED
  7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION. AT MAXIMUM MATERIAL CONDITION.

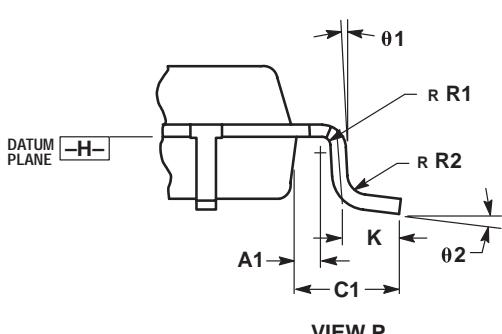
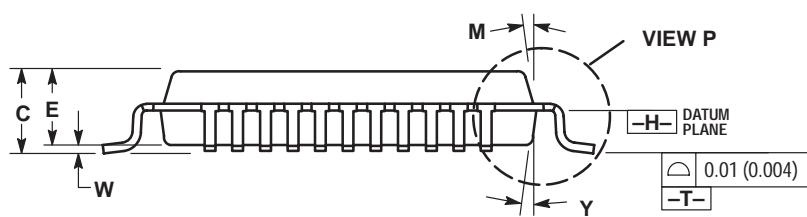
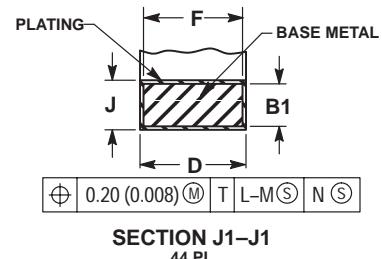
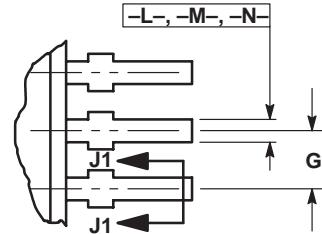
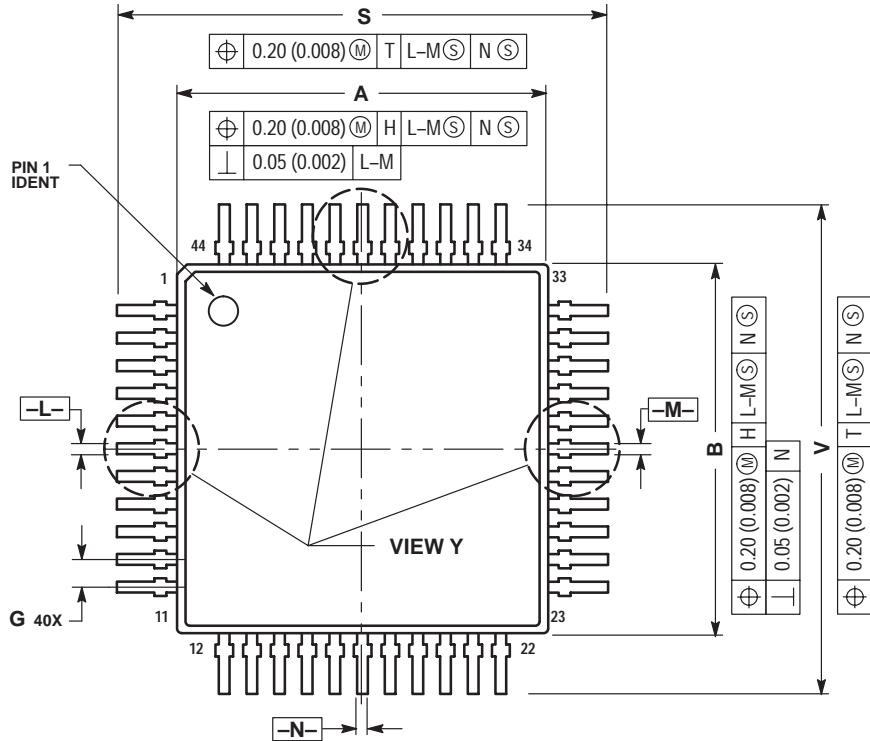
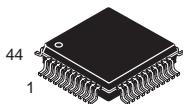
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.681	0.694	17.298	17.627
B	0.784	0.792	19.914	20.116
C	0.173	0.181	4.395	4.597
D	0.024	0.031	0.610	0.787
E	0.058	0.062	1.473	1.574
F	0.016	0.023	0.407	0.584
G	0.050 BSC		1.270 BSC	
H	0.110 BSC		2.794 BSC	
J	0.018	0.024	0.458	0.609
K	1.078	1.086	27.382	27.584
Q	0.148	0.151	3.760	3.835
R	0.416	0.426	10.567	10.820
U	0.110 BSC		2.794 BSC	
Y	0.503 REF		12.776 REF	

**FTB SUFFIX**  
**CASE 824D-01**  
Plastic Package  
(TQFP-44)  
ISSUE O



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.950	10.050	0.392	0.396
B	9.950	10.050	0.392	0.396
C	1.400	1.600	0.055	0.063
D	0.300	0.450	0.012	0.018
E	1.350	1.450	0.053	0.057
F	0.300	0.400	0.012	0.016
G	0.800 BSC		0.031 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.450	0.550	0.018	0.022
L	8.000 BSC		0.315 BSC	
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
Q	1°	5°	1°	5°
R	0.100	0.200	0.004	0.008
S	11.900	12.100	0.469	0.476
V	11.900	12.100	0.469	0.476
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	
Y	12° REF		12° REF	

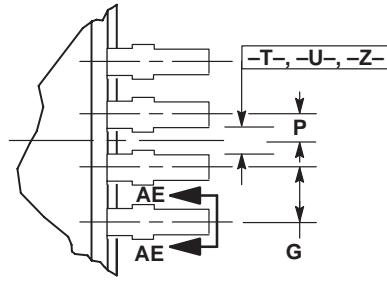
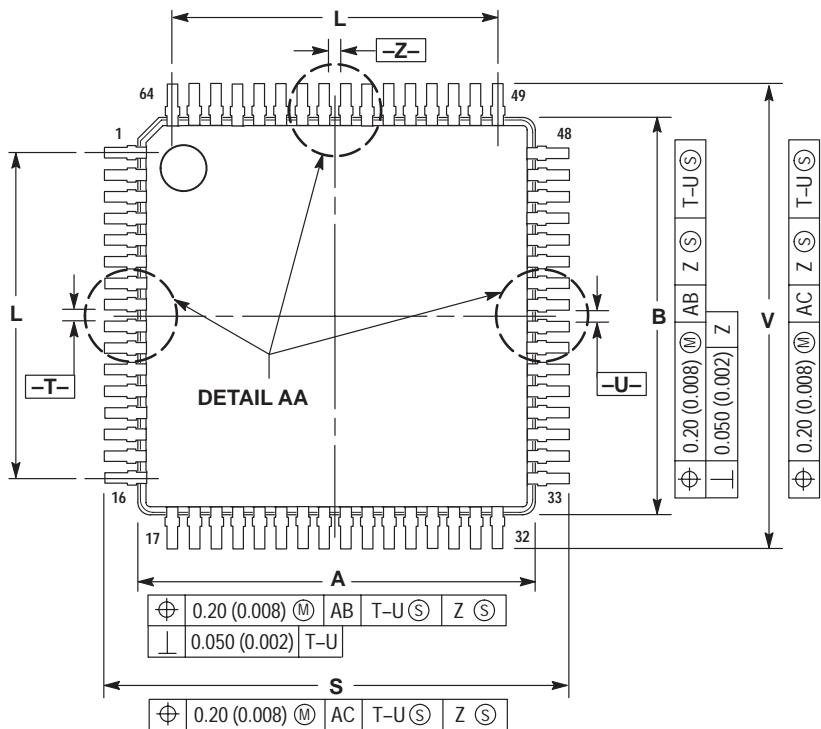
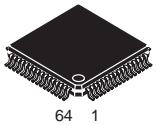
**FB SUFFIX**  
**CASE 824E-02**  
Plastic Package  
(QFP)  
ISSUE A



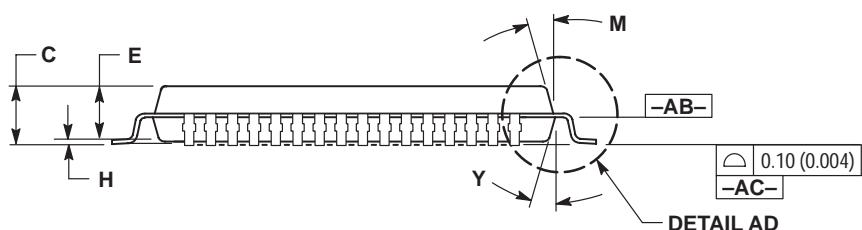
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
  4. DATUMS -L-, -M- AND -N- TO BE DETERMINED AT DATUM PLANE -H-.
  5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -T-.
  6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
  7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.530 (0.021).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.90	10.10	0.390	0.398
B	9.90	10.10	0.390	0.398
C	2.00	2.21	0.079	0.087
D	0.30	0.45	0.0118	0.0177
E	2.00	2.10	0.079	0.083
F	0.30	0.40	0.012	0.016
G	0.80	BSC	0.031	BSC
J	0.13	0.23	0.005	0.009
K	0.65	0.95	0.026	0.037
M	5°	10°	5°	10°
S	12.95	13.45	0.510	0.530
V	12.95	13.45	0.510	0.530
W	0.000	0.210	0.000	0.008
Y	5°	10°	5°	10°
A1	0.450	REF	0.018	REF
B1	0.130	0.170	0.005	0.007
C1	1.600	REF	0.063	REF
R1	0.130	0.300	0.005	0.012
R2	0.130	0.300	0.005	0.012
θ1	5°	10°	5°	10°
θ2	0°	7°	0°	7°

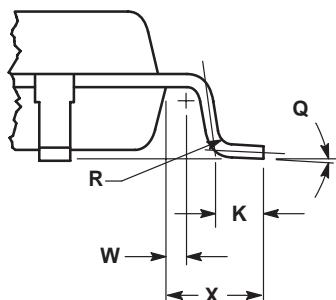
**FB SUFFIX**  
**CASE 840F-01**  
Plastic Package  
ISSUE O



DETAIL AA



SECTION AE-AE

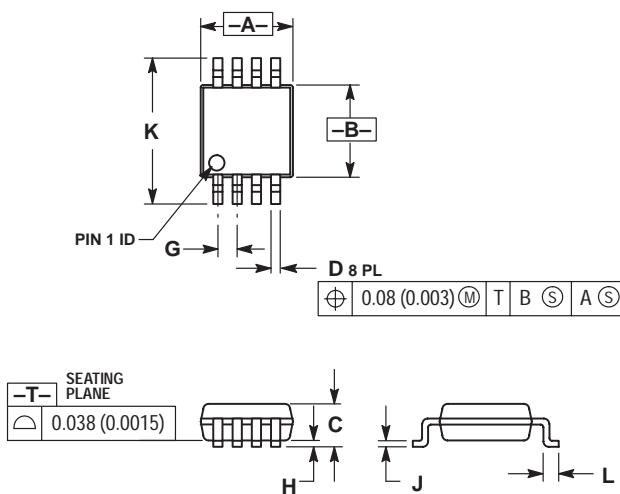


DETAIL AD

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
  4. DATUMS -T-, -U- AND -Z- TO BE DETERMINED AT DATUM PLANE -AC-.
  5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
  6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
  7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.950	10.050	0.392	0.396
B	9.950	10.050	0.392	0.396
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500 BSC		0.020 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.450	0.550	0.018	0.022
L	7.500 BSC		0.295 BSC	
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250 BSC		0.010 BSC	
Q	1°	5°	1°	5°
R	0.100	0.200	0.004	0.008
S	11.900	12.100	0.469	0.476
V	11.900	12.100	0.469	0.476
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	
Y	12° REF		12° REF	

**DM SUFFIX**  
**CASE 846A-02**  
 Plastic Package  
 (Micro-8)  
 ISSUE C

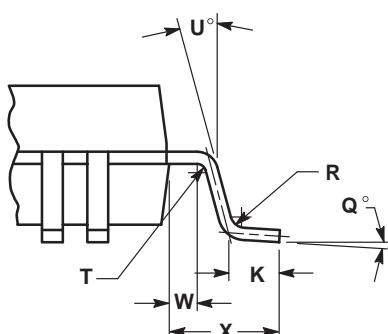
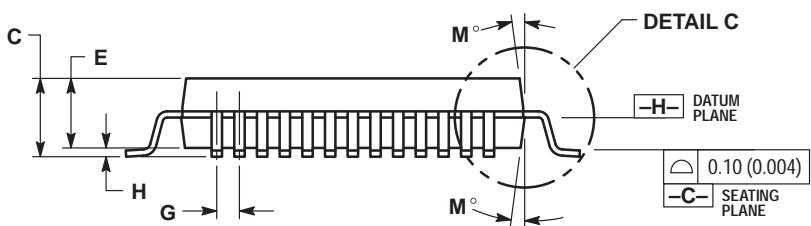
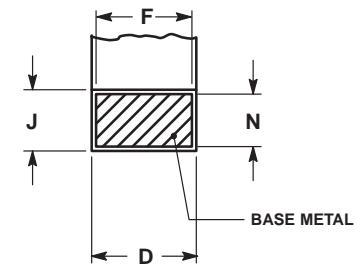
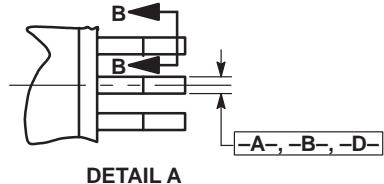
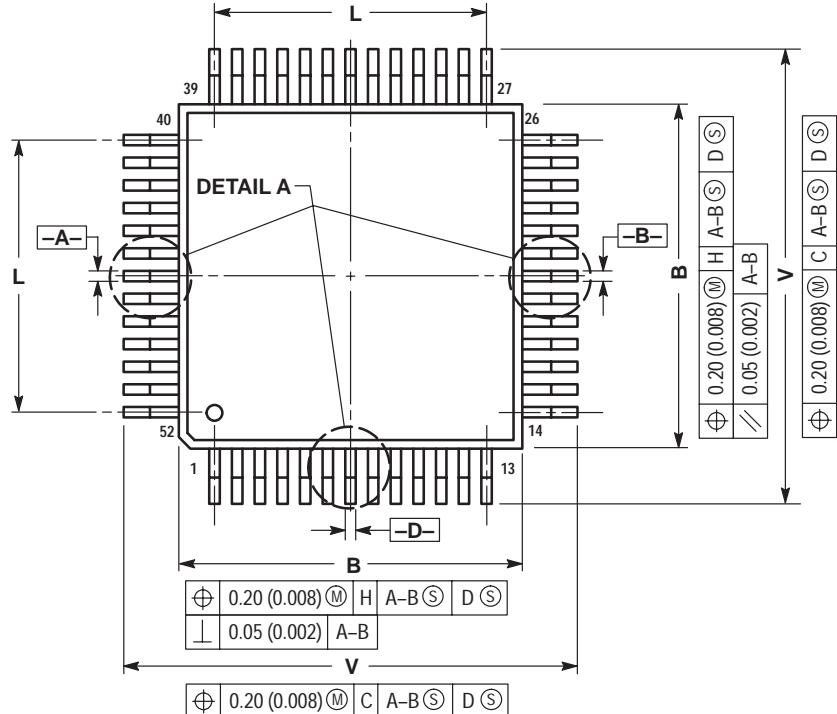
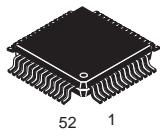


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	---	1.10	---	0.043
D	0.25	0.40	0.010	0.016
G	0.65 BSC		0.026 BSC	
H	0.05	0.15	0.002	0.006
J	0.13	0.23	0.005	0.009
K	4.75	5.05	0.187	0.199
L	0.40	0.70	0.016	0.028

**FB SUFFIX**  
**CASE 848B-04**  
Plastic Package  
(TQFP-52)  
ISSUE C

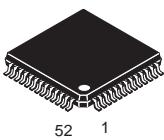


**DETAIL C**

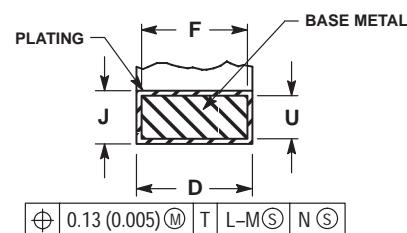
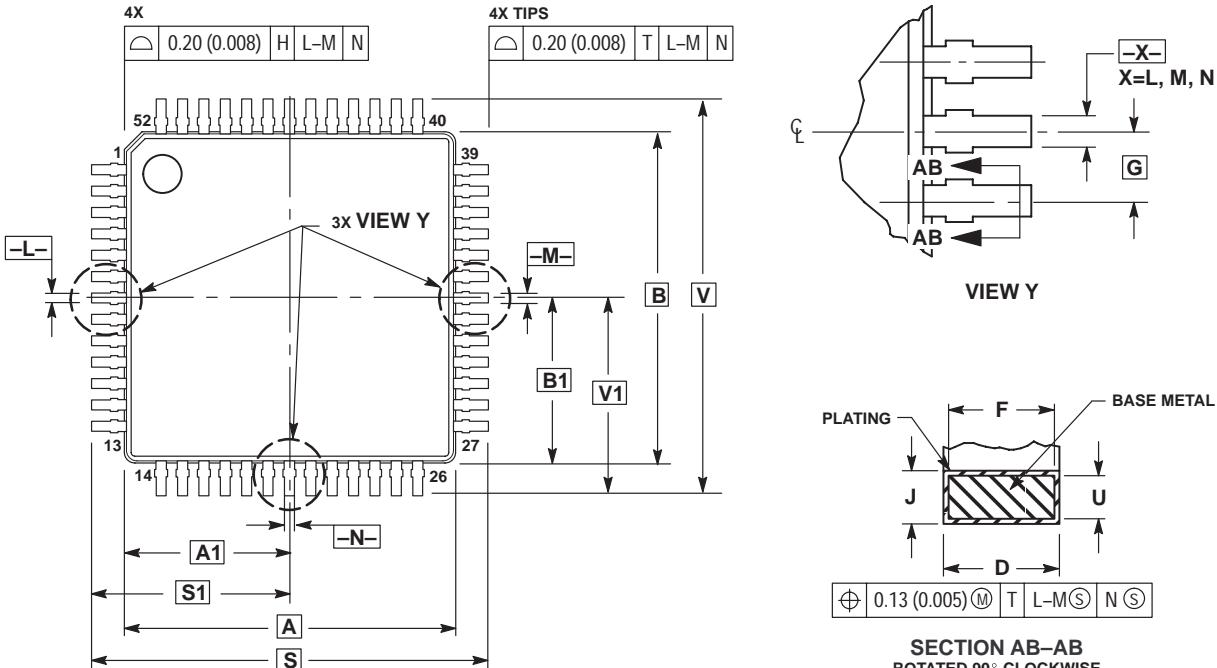
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
  4. DATUMS -A-, -B-, AND -D- TO BE DETERMINED AT DATUM PLANE -H-.
  5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -C-.
  6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
  7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.90	10.10	0.390	0.398
B	9.90	10.10	0.390	0.398
C	2.10	2.45	0.083	0.096
D	0.22	0.38	0.009	0.015
E	2.00	2.10	0.079	0.083
F	0.22	0.33	0.009	0.013
G	0.65	BSCL	0.026	BSCL
H	—	0.25	—	0.010
J	0.13	0.23	0.005	0.009
K	0.65	0.95	0.026	0.037
L	7.80	REF	0.307	REF
M	5°	10°	5°	10°
N	0.13	0.17	0.005	0.007
Q	0°	7°	0°	7°
R	0.13	0.30	0.005	0.012
S	12.95	13.45	0.510	0.530
T	0.13	—	0.005	—
U	0°	—	0°	—
V	12.95	13.45	0.510	0.530
W	0.35	0.45	0.014	0.018
X	1.6	REF	0.063	REF

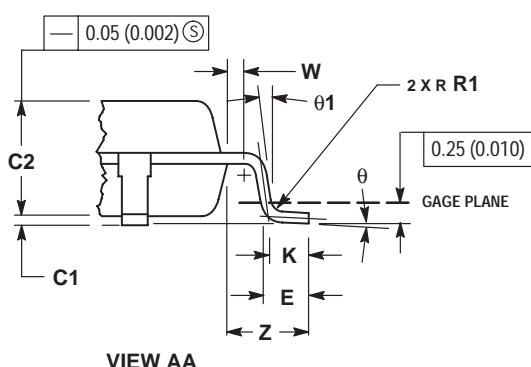
**FB SUFFIX**  
**CASE 848D-03**  
Plastic Package  
ISSUE C



52 1



SECTION AB-AB  
ROTATED 90° CLOCKWISE

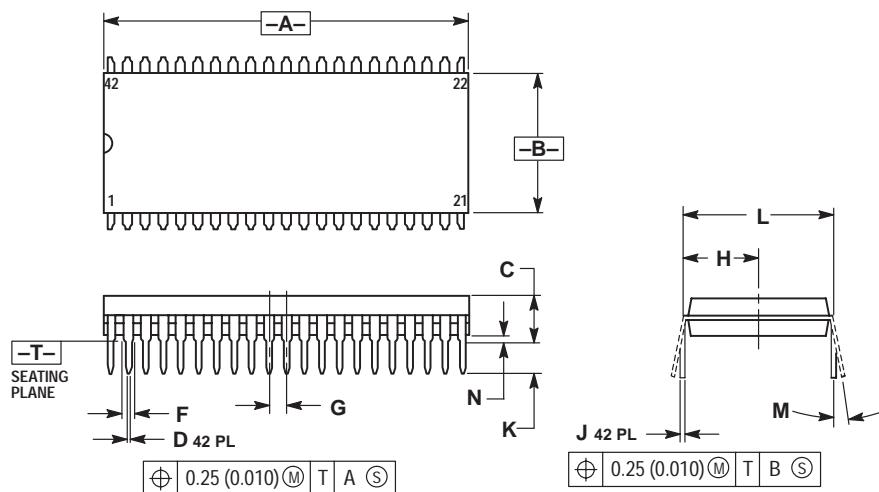
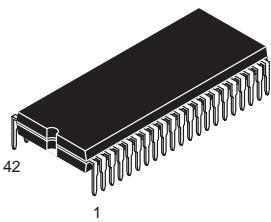


NOTES:

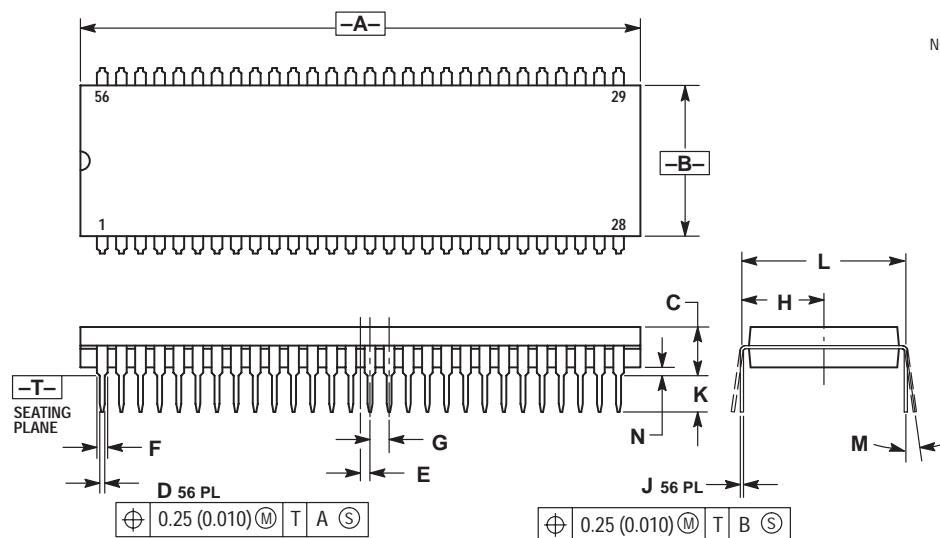
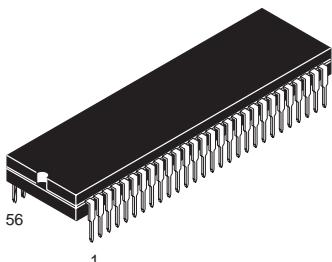
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -L-, -M- AND -N- TO BE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -T-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.46 (0.018). MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 (0.003).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.00	BSC	0.394	BSC
A1	5.00	BSC	0.197	BSC
B	10.00	BSC	0.394	BSC
B1	5.00	BSC	0.197	BSC
C	—	1.70	—	0.067
C1	0.05	0.20	0.002	0.008
C2	1.30	1.50	0.051	0.059
D	0.20	0.40	0.008	0.016
E	0.45	0.75	0.018	0.030
F	0.22	0.35	0.009	0.014
G	0.65	BSC	0.026	BSC
J	0.07	0.20	0.003	0.008
K	0.50	REF	0.020	REF
R1	0.08	0.20	0.003	0.008
S	12.00	BSC	0.472	BSC
S1	6.00	BSC	0.236	BSC
U	0.09	0.16	0.004	0.006
V	12.00	BSC	0.472	BSC
V1	6.00	BSC	0.236	BSC
W	0.20	REF	0.008	REF
Z	1.00	REF	0.039	REF
θ	0°	7°	0°	7°
θ1	0°	—	0°	—
θ2	12°	REF	12°	REF
θ3	5°	13°	5°	13°

**B SUFFIX**  
**CASE 858-01**  
Plastic Package  
ISSUE O



**B SUFFIX**  
**CASE 859-01**  
Plastic Package  
(SDIP)  
ISSUE O

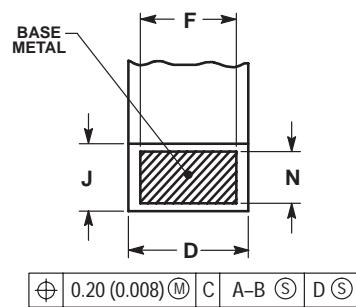
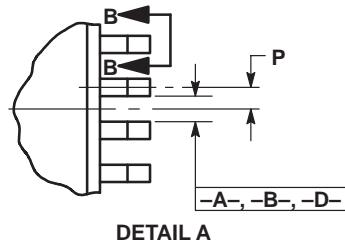
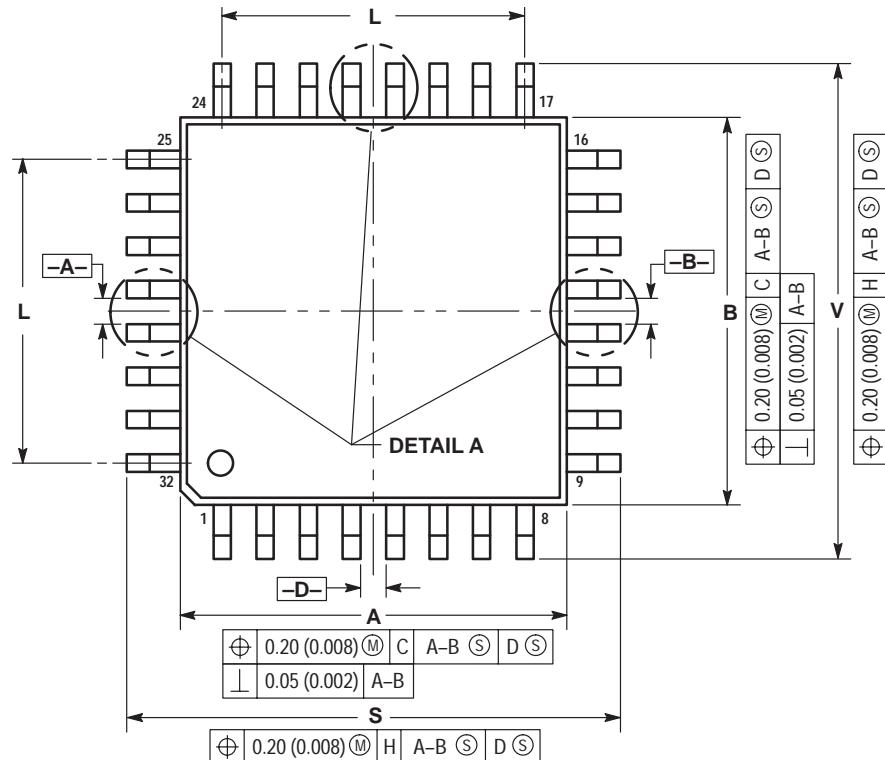


**FB, FTB SUFFIX**
**CASE 873-01**

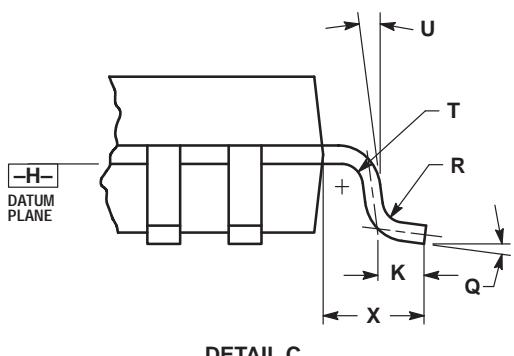
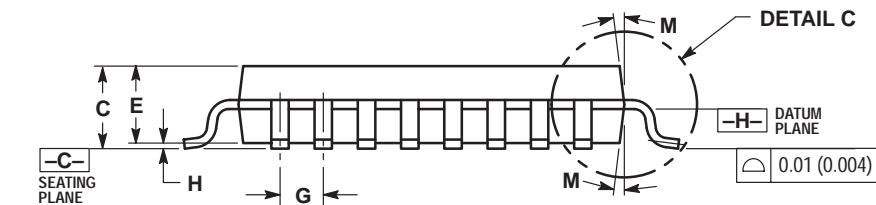
Plastic Package

(TQFP-32)

ISSUE A



**SECTION B-B**  
VIEW ROTATED 90° CLOCKWISE

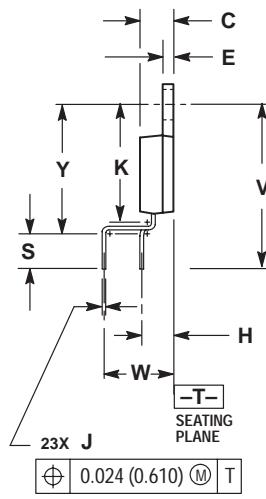
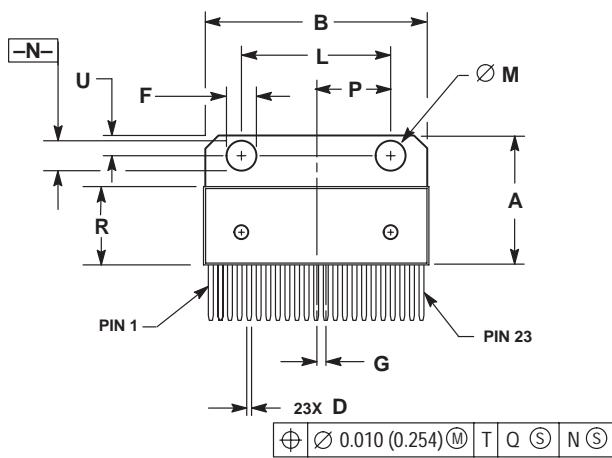
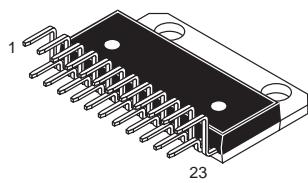


## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -A-, -B- AND -D- TO BE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -C-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.95	7.10	0.274	0.280
B	6.95	7.10	0.274	0.280
C	1.40	1.60	0.055	0.063
D	0.273	0.373	0.010	0.015
E	1.30	1.50	0.051	0.059
F	0.273	—	0.010	—
G	0.80	BSC	0.031	BSC
H	—	0.20	—	0.008
J	0.119	0.197	0.005	0.008
K	0.33	0.57	0.013	0.022
L	5.6	REF	0.220	REF
M	6°	8°	6°	8°
N	0.119	0.135	0.005	0.005
P	0.40	BSC	0.016	BSC
Q	5°	10°	5°	10°
R	0.15	0.25	0.006	0.010
S	8.85	9.15	0.348	0.360
T	0.15	0.25	0.006	0.010
U	5°	11°	5°	11°
V	8.85	9.15	0.348	0.360
X	1.00	REF	0.039	REF

**T SUFFIX**  
**CASE 894-03**  
 Plastic Package  
 (23-Pin SZIP)  
 ISSUE B

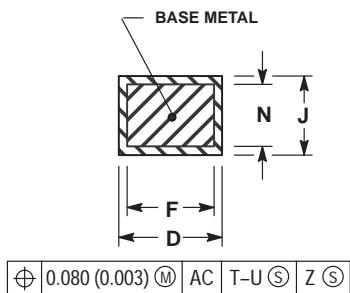
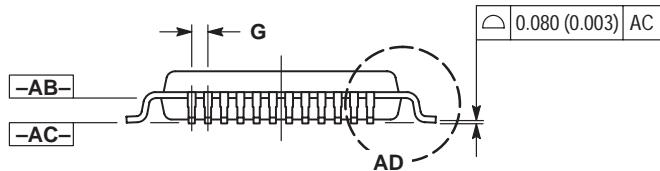
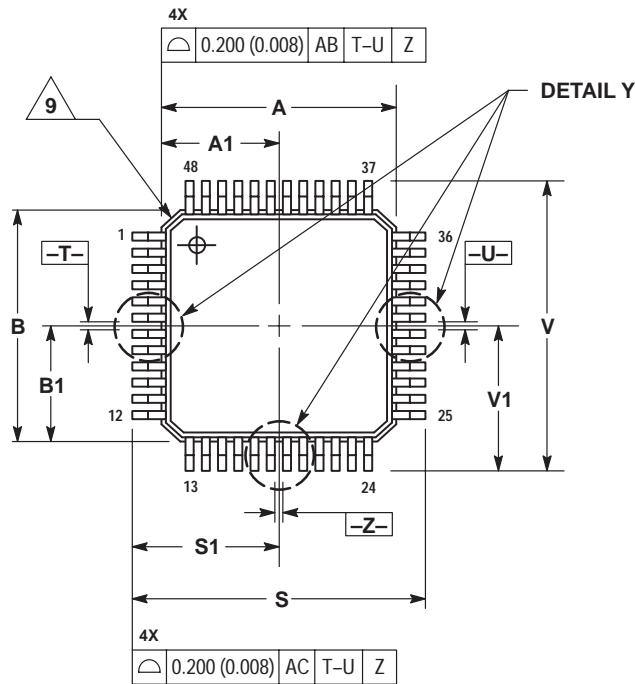
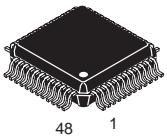


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
6. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.684	0.694	17.374	17.627
B	1.183	1.193	30.048	30.302
C	0.175	0.179	4.445	4.547
D	0.026	0.031	0.660	0.787
E	0.058	0.062	1.473	1.574
F	0.165	0.175	4.191	4.445
G	0.050	BSC	1.270	BSC
H	0.169	BSC	4.293	BSC
J	0.014	0.020	0.356	0.508
K	0.625	0.639	15.875	16.231
L	0.770	0.790	19.558	20.066
M	0.148	0.152	3.760	3.861
N	0.148	0.152	3.760	3.861
P	0.390	BSC	9.906	BSC
R	0.416	0.424	10.566	10.770
S	0.157	0.167	3.988	4.242
U	0.105	0.115	2.667	2.921
V	0.868	REF	22.047	REF
W	0.200	BSC	5.080	BSC
Y	0.700	0.710	17.780	18.034

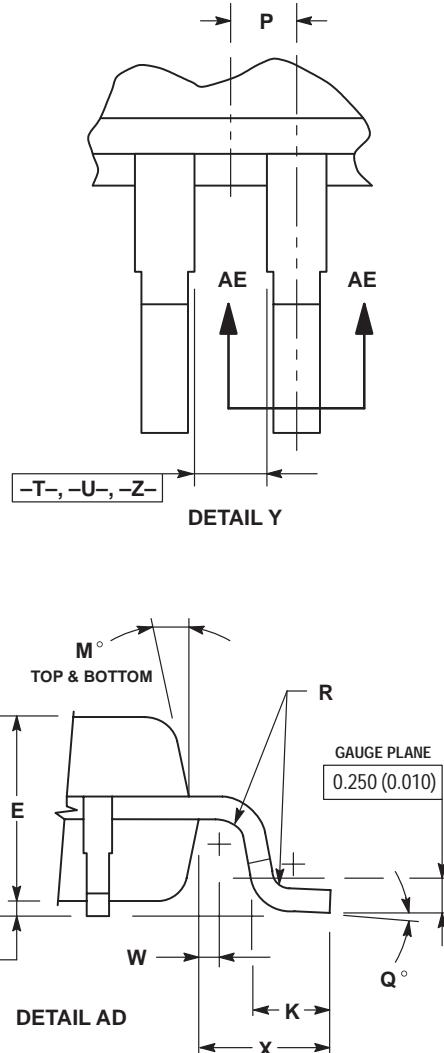
**FTA SUFFIX**  
**CASE 932-02**  
Plastic Package  
(TQFP-48)  
ISSUE D



**SECTION AE-AE**

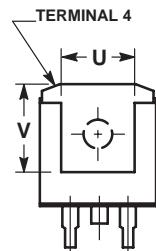
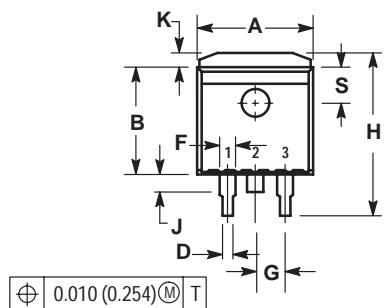
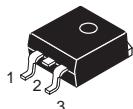
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO NOT INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.000	BSC	0.276	BSC
A1	3.500	BSC	0.138	BSC
B	7.000	BSC	0.276	BSC
B1	3.500	BSC	0.138	BSC
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.009
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500	BASIC	0.020	BASIC
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12 °REF		12 °REF	
N	0.090	0.160	0.004	0.006
P	0.250	BASIC	0.010	BASIC
Q	1 °	5 °	1 °	5 °
R	0.150	0.250	0.006	0.010
S	9.000	BSC	0.354	BSC
S1	4.500	BSC	0.177	BSC
V	9.000	BSC	0.354	BSC
V1	4.500	BSC	0.177	BSC
W	0.200	REF	0.008	REF
X	1.000	REF	0.039	REF

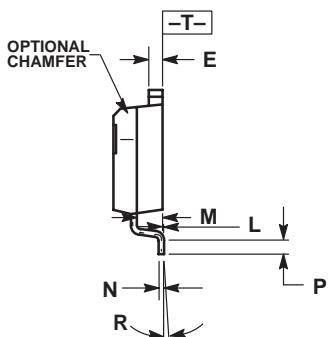
**D2T SUFFIX**  
**CASE 936-03**  
 Plastic Package  
 ISSUE B



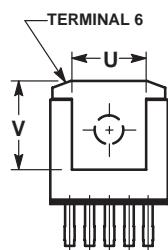
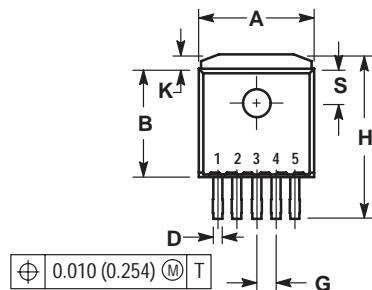
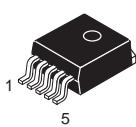
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 4.
5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.386	0.403	9.804	10.236
B	0.356	0.368	9.042	9.347
C	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
E	0.045	0.055	1.143	1.397
F	0.051	REF	1.295	REF
G	0.100	BSC	2.540	BSC
H	0.539	0.579	13.691	14.707
J	0.125	MAX	3.175	MAX
K	0.050	REF	1.270	REF
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	5°	REF	5°	REF
S	0.116	REF	2.946	REF
U	0.200	MIN	5.080	MIN
V	0.250	MIN	6.350	MIN



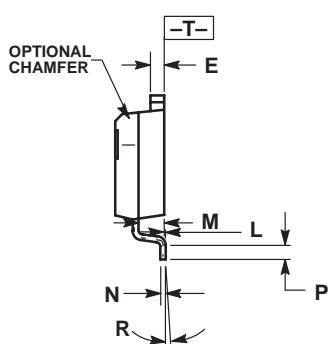
**D2T SUFFIX**  
**CASE 936A-02**  
 Plastic Package  
 (D<sup>2</sup>PAK)  
 ISSUE A



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 6.
5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.386	0.403	9.804	10.236
B	0.356	0.368	9.042	9.347
C	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
E	0.045	0.055	1.143	1.397
G	0.067	BSC	1.702	BSC
H	0.539	0.579	13.691	14.707
K	0.050	REF	1.270	REF
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	5°	REF	5°	REF
S	0.116	REF	2.946	REF
U	0.200	MIN	5.080	MIN
V	0.250	MIN	6.350	MIN

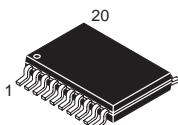


## **DT, DTB SUFFIX**

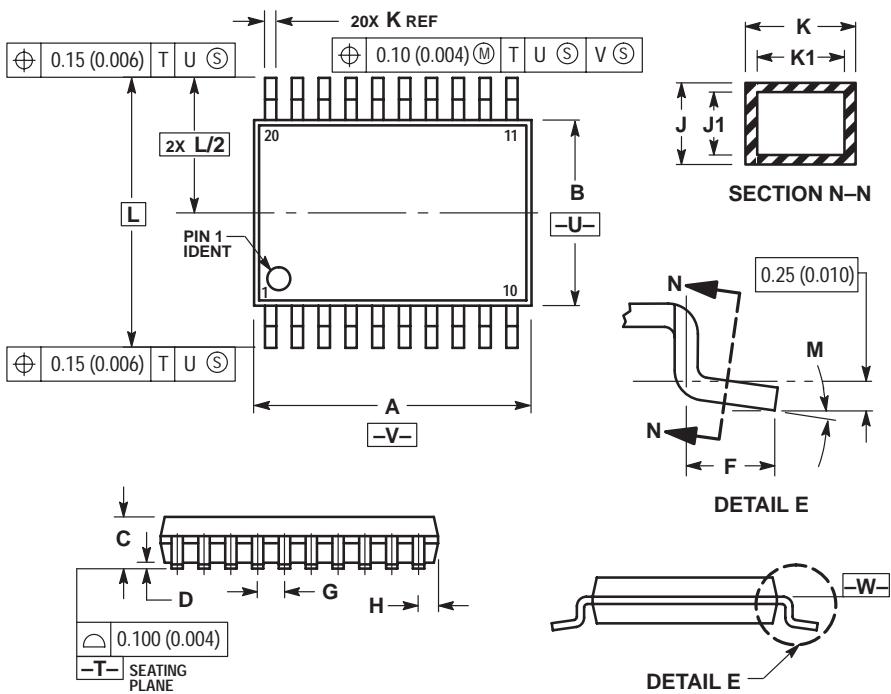
CASE 948E-02

Plastic Package

(TSSOP=20)



(1800)  
ISSUE A



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40	BSC	0.252	BSC
M	0°	8°	0°	8°

DTB SUFFIX

CASE 948F-01

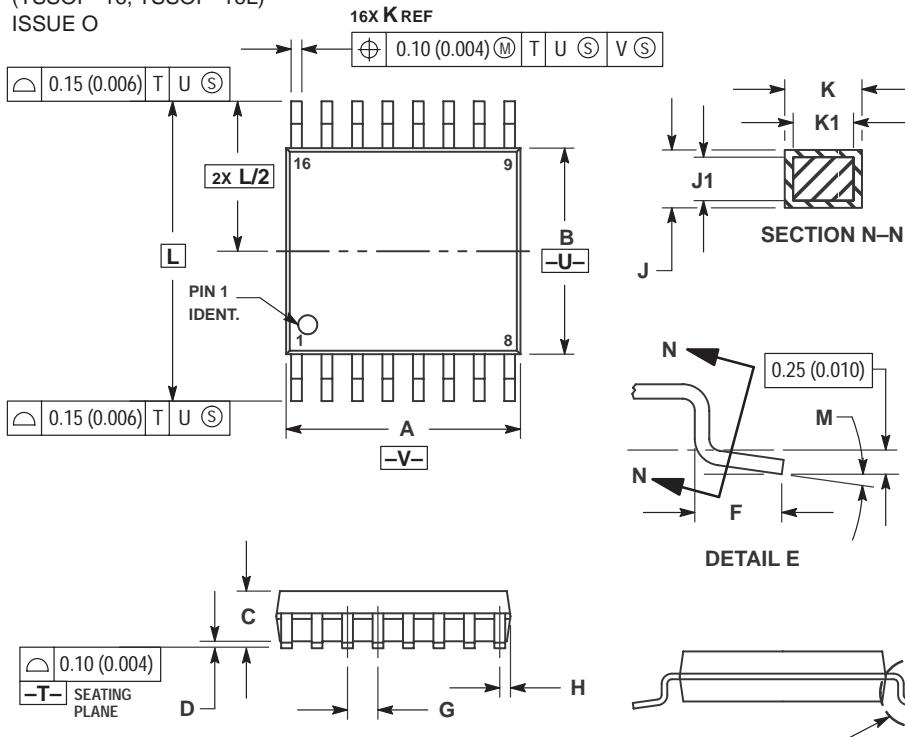
### **Plastic Package**

Plastic Package  
(TSSOP-16, TSSOP-16L)

(ISSUE 0)



Plastic Package  
(TSSOP-16, TSSOP-16L)  
ISSUE 0



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40	BSC	0.252	BSC
M	0°	9°	0°	9°

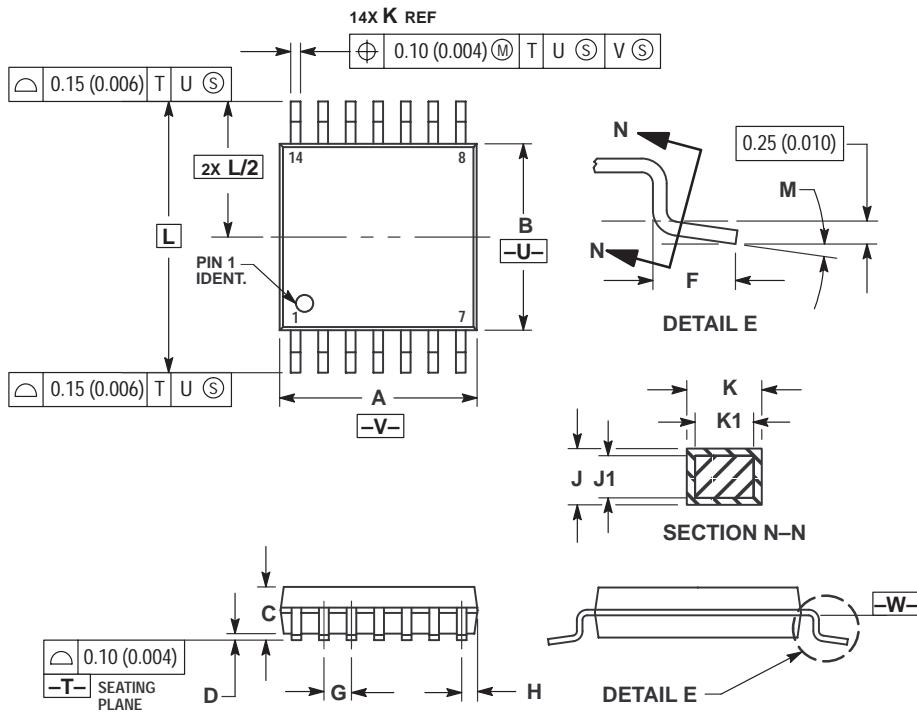
DTB SUFFIX

CASE 948G-01

Plastic Package

(TSSOP-14)

ISSUE O

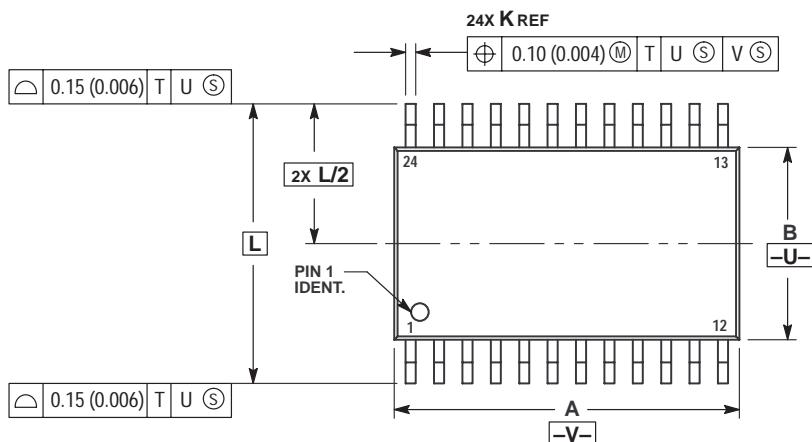
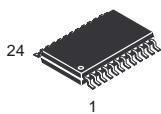


NOTES:

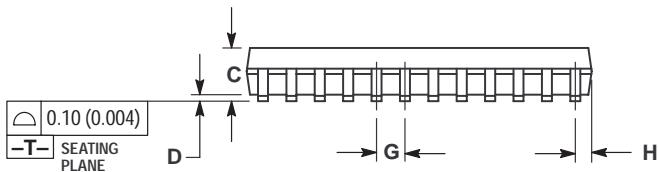
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: MILLIMETER.
- 3 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- 5 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 6 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 7 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	—	—	0.047	—
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC	—	0.026 BSC	—
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC	—	0.252 BSC	—
M	0°	8°	0°	8°

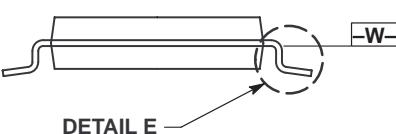
**DTB SUFFIX**  
**CASE 948H-01**  
 Plastic Package  
 ISSUE O



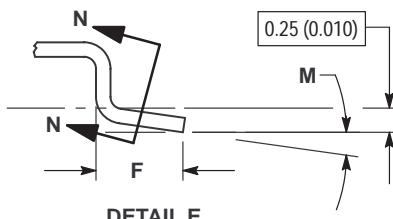
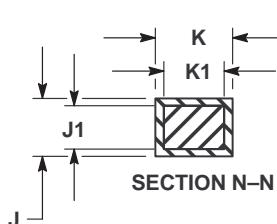
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.70	7.90	0.303	0.311
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC	—	0.026 BSC	—
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC	—	0.252 BSC	—
M	0°	8°	0°	8°

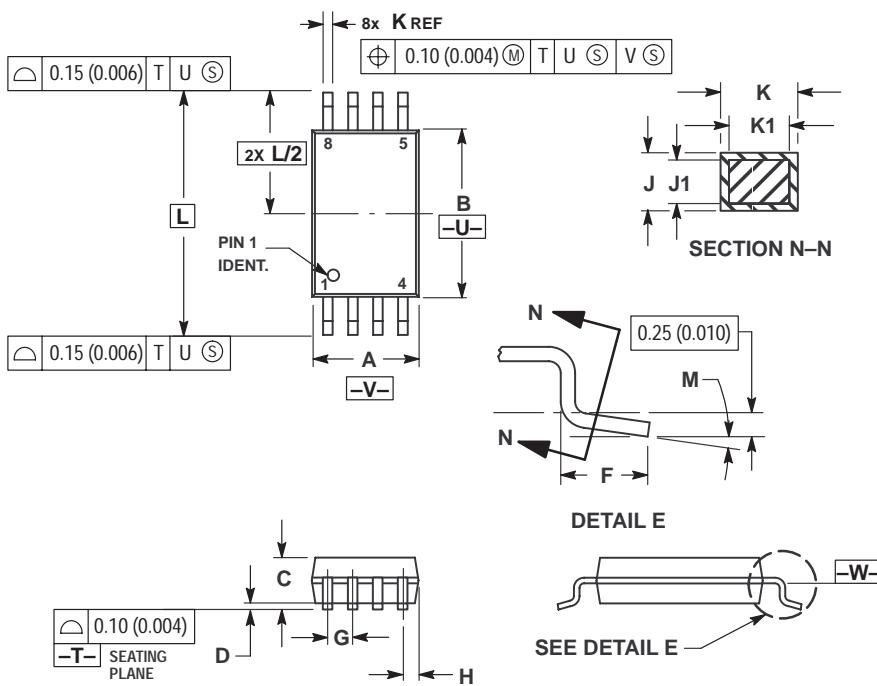


DETAIL E



DETAIL E

**DTB SUFFIX  
CASE 948J-01**  
Plastic Package  
(TSSOP-8)  
**ISSUE Q**



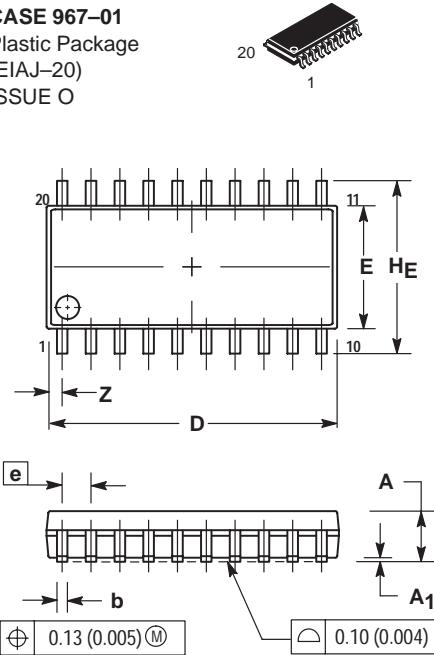
## NOTES:

- NOTE:**

  - 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  - 2 CONTROLLING DIMENSION: MILLIMETER.
  - 3 DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  - 4 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  - 5 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  - 6 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  - 7 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40	BSC	0.252	BSC
M	0°	8°	0°	8°

**M SUFFIX  
CASE 967-01**  
Plastic Package  
(EIAJ-20)  
**ISSUE O**

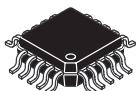


NOTES:

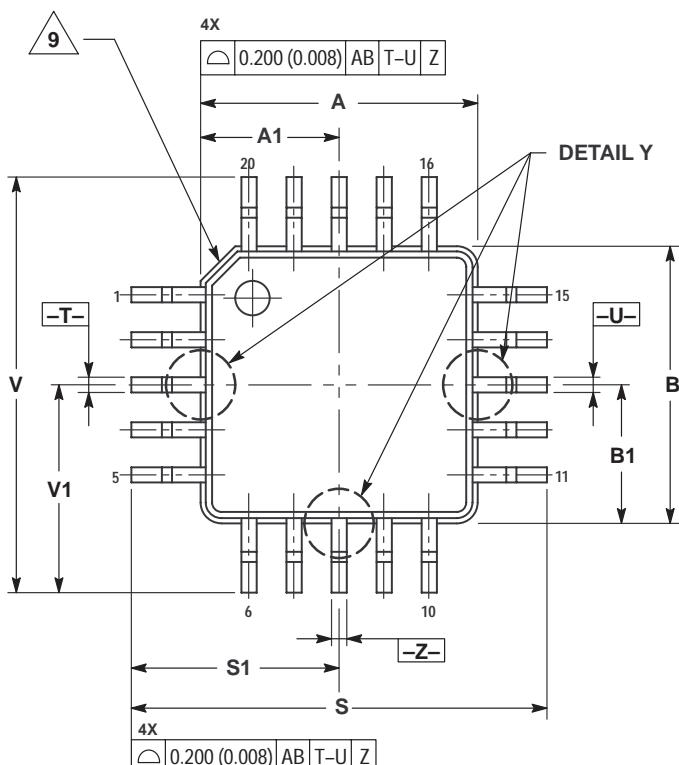
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: MILLIMETER.
- 3 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 5 THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	—	2.05	—	0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27	BSC	0.050	BSC
H <sub>F</sub>	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L <sub>F</sub>	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
O <sub>1</sub>	0.70	0.90	0.028	0.035
Z	—	0.81	—	0.032

**FTB SUFFIX**  
**CASE 976-01**  
Plastic Package  
(TQFP-20)  
ISSUE O



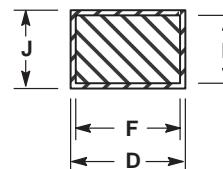
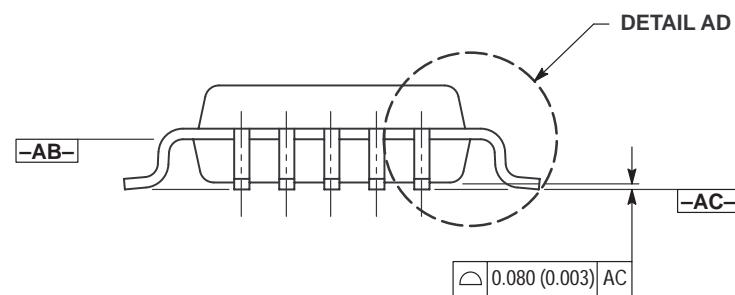
20 1



NOTES:

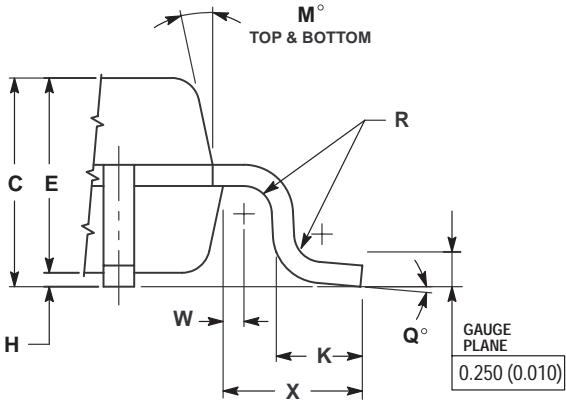
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
5. DIMENSIONS S AND V TO BE DETERMINED AT DATUM PLANE -AC-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO NOT INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.003).
9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.000	BSC	0.157	BSC
A1	2.000	BSC	0.079	BSC
B	4.000	BSC	0.157	BSC
B1	2.000	BSC	0.079	BSC
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.650	BSC	0.026	BSC
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250	BSC	0.010	BSC
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	6.000	BSC	0.236	BSC
S1	3.000	BSC	0.118	BSC
V	6.000	BSC	0.236	BSC
V1	3.000	BSC	0.118	BSC
W	0.200	REF	0.008	REF
X	1.000	REF	0.039	REF

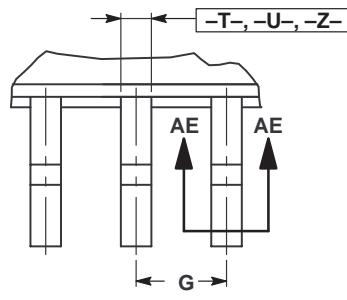


(+) 0.080 (0.003) (S) AC T-U (S) Z (S)

**SECTION AE-AE**

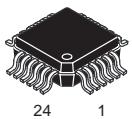


DETAIL AD

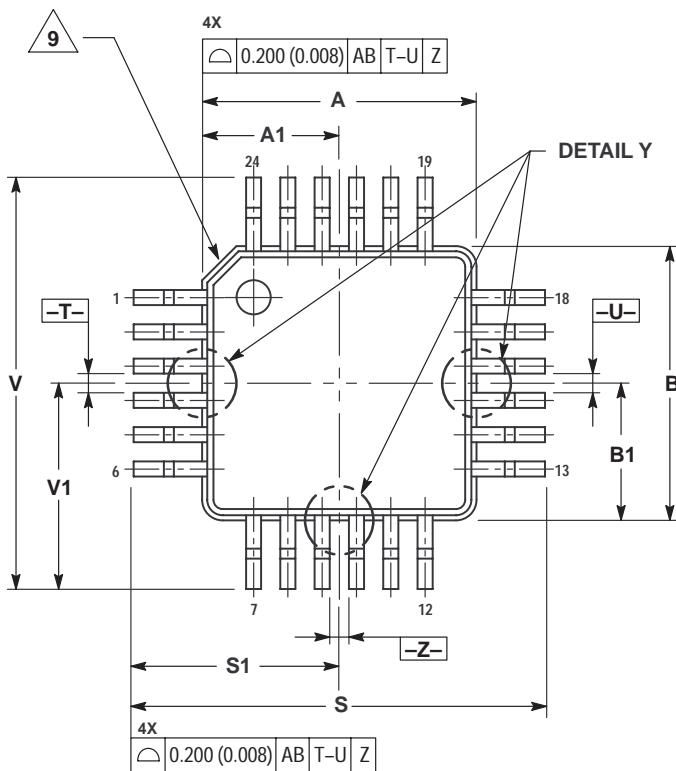


DETAIL Y

**FTA SUFFIX**  
**CASE 977-01**  
 Plastic Package  
 ISSUE O



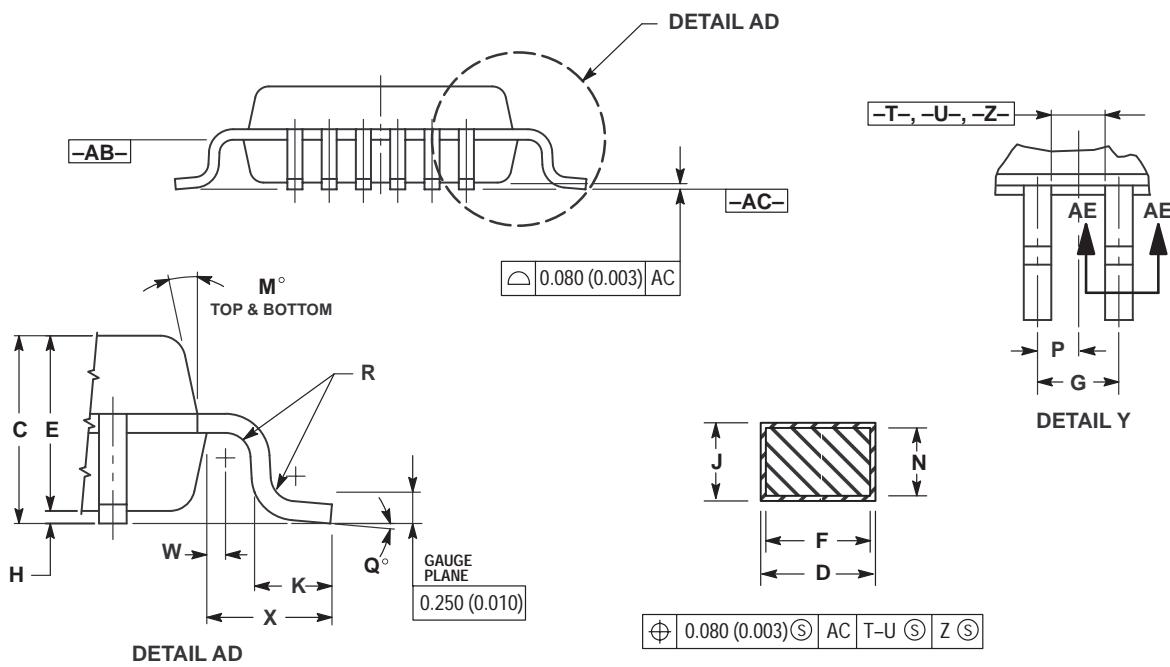
24 1



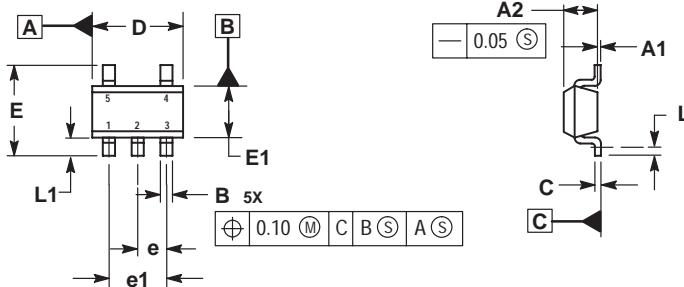
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
5. DIMENSIONS S AND V TO BE DETERMINED AT DATUM PLANE -AC-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
7. DATUM D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.003).
9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.000	BSC	0.157	BSC
A1	2.000	BSC	0.079	BSC
B	4.000	BSC	0.157	BSC
B1	2.000	BSC	0.079	BSC
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500	BSC	0.020	BSC
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12°	REF	12°	REF
N	0.090	0.160	0.004	0.006
P	0.250	BSC	0.010	BSC
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	6.000	BSC	0.236	BSC
S1	3.000	BSC	0.118	BSC
V	6.000	BSC	0.236	BSC
V1	3.000	BSC	0.118	BSC
W	0.200	REF	0.008	REF
X	1.000	REF	0.039	REF



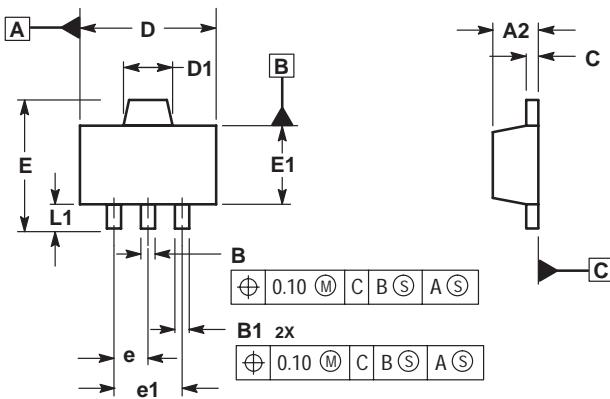
**N SUFFIX**  
**CASE 1212-01**  
Plastic Package  
(SOT-23)  
ISSUE O



NOTES:  
1. DIMENSIONS ARE IN MILLIMETERS.  
2. INTERPRET DIMENSIONS AND TOLERANCES  
PER ASME Y14.5M, 1994.  
3. DATUM C IS A SEATING PLANE.

	MILLIMETERS	
DIM	MIN	MAX
A1	0.00	0.10
A2	1.00	1.30
B	0.30	0.50
C	0.10	0.25
D	2.80	3.00
E	2.50	3.10
E1	1.50	1.80
e	0.95 BSC	
e1	1.90 BSC	
L	0.20	---
L1	0.45	0.75

**H SUFFIX**  
**CASE 1213-01**  
Plastic Package  
(SOT-89)  
ISSUE O



NOTES:  
1. DIMENSIONS ARE IN MILLIMETERS.  
2. INTERPRET DIMENSIONS AND TOLERANCING  
PER ASME Y14.5M, 1994.  
3. DATUM C IS A SEATING PLANE.

	MILLIMETERS	
DIM	MIN	MAX
A2	1.40	1.60
B	0.37	0.57
B1	0.32	0.52
C	0.30	0.50
D	4.40	4.60
D1	1.50	1.70
E	----	4.25
E1	2.40	2.60
e	1.50 BSC	
e1	3.00 BSC	
L1	0.80	---